



Overview of the CMS strip and pixel detectors

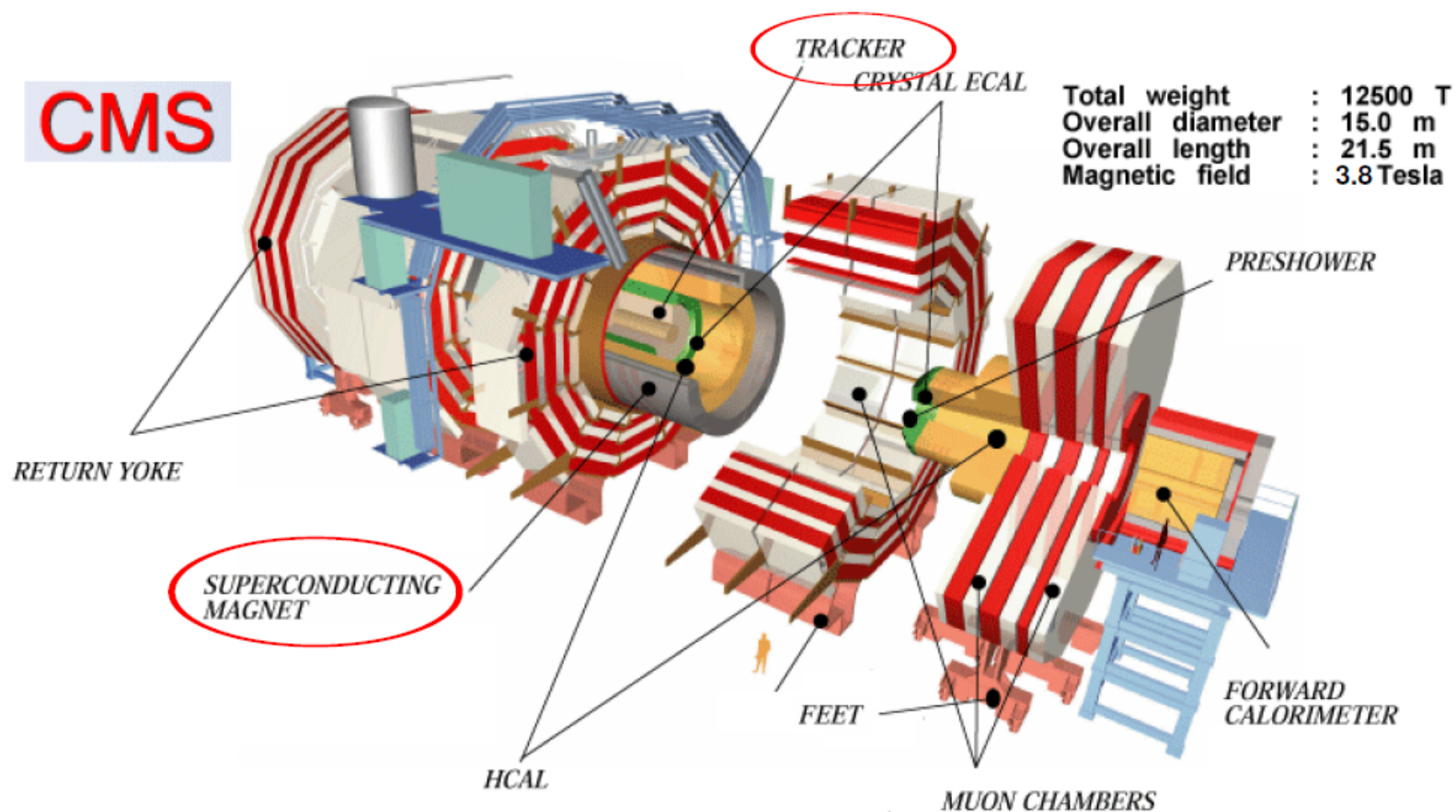
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On behalf of the CMS Tracker collaboration

Université catholique de Louvain
Center for Cosmology, Particle Physics and Phenomenology

Vertex2013

16th of September 2013

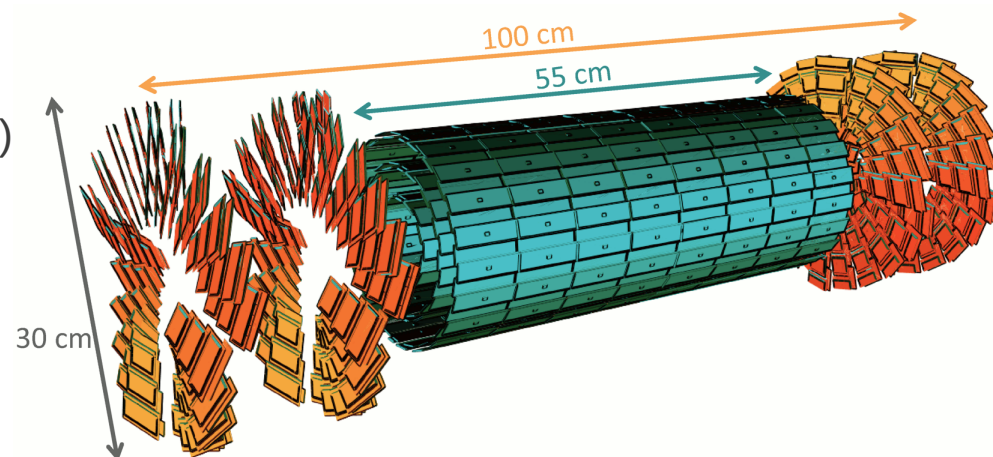
- Status at the end of the data taking
- Performances and alignment
- Evolution with integrated luminosity



- Silicon pixel + Strip detector with optical analog readout

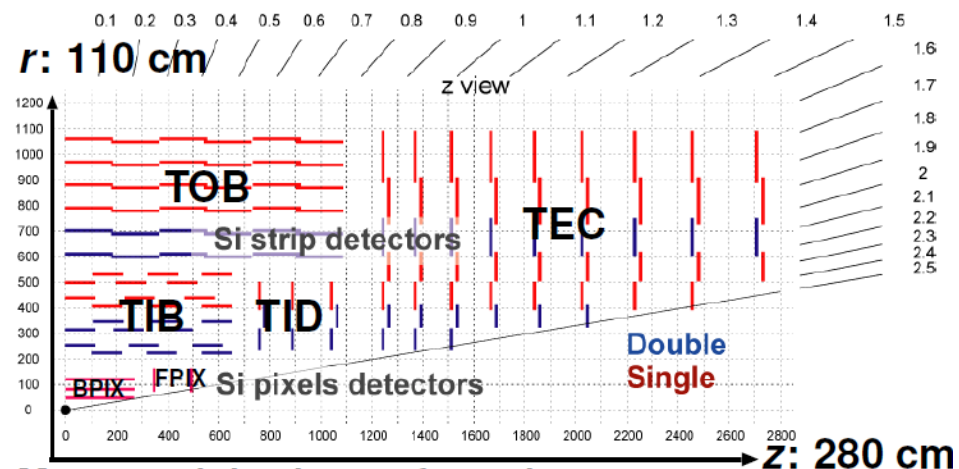
- **Pixel :**

- N+ in n sensors :
 - 100 μm x 150 μm
 - 52x80 pixel read by one ReadOut Chip (ROC)
- **Barrel (Bpix):**
 - 3 layers (56cm long) at $r= 4.3, 7.2, 11.0$ cm
 - 48M pixels, 11520 ROCs, 1120 RO links
- **Endcap (FPix) :**
 - 4 disks inner (outer) radius=6 (15) cm at $z= \pm 34.5, \pm 46.5$ cm
 - 18M pixels, 4320 ROCs, 192 RO links



- **Strip :**

- 9.3M strips in 15148 modules :
 - Inner: 4 layers barrel (TIB), 3 disks (TID) cap
 - Outer: 6 layers barrel (TOB), 9 disks (TEC) cap
- 200m² silicon sensor (p-in-n) :
 - Pitch from 80 to 205 μm
 - 20 < r < 55 cm thin ($d=320$ μm)
 - $r > 55$ cm thick ($d=500$ μm)
- Generally measure $r\phi$ direction
- Some radii ('Stereo'):
 - additional 2nd modules rotated by 100 mrad
 - measurements for $\eta(\text{track})$



Tracker state @ end of data taking



CMS Data: a few figures



• Luminosity :

Period	\sqrt{s} (TeV)	Delivered Lumi (fb^{-1})	Data Taking Efficiency (%)	Validated Data (%)
2010	7	0.0442	92.2	88.6
2011	7	6.13	90.5	90.1
2012	8	23.3	93.5	90

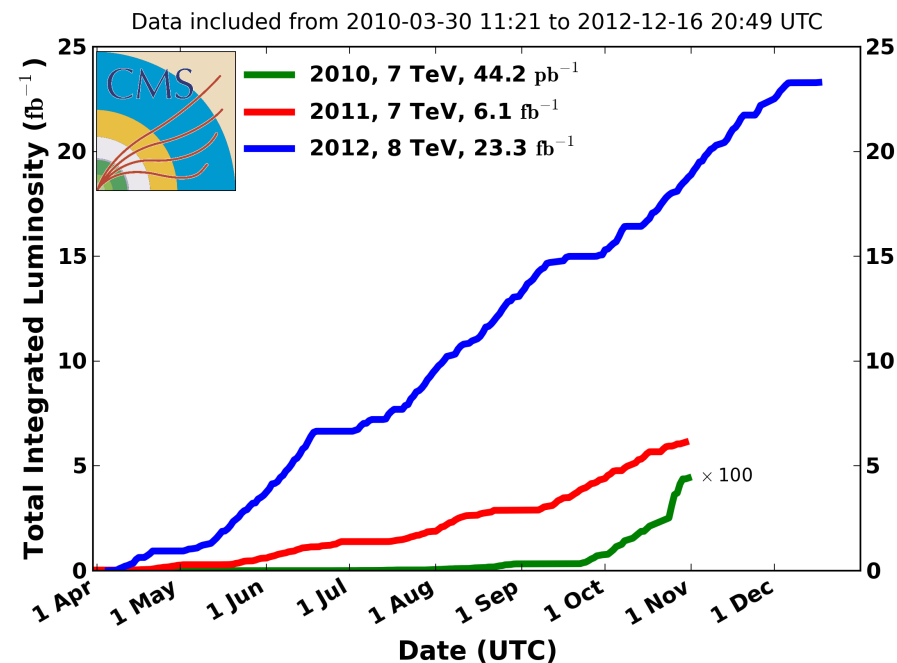
- 4.5 (1.7)% loss due to downtime (deadtime)
- 77 % design inst. Luminosity reached with a 50ns bunch spacing

• Pile up:

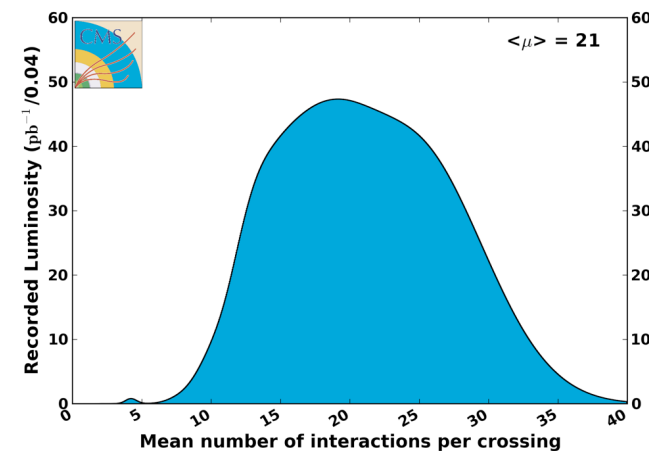
- Average in 2012: 21 interaction/bunch crossing
- Peak PU (except high PU runs) :

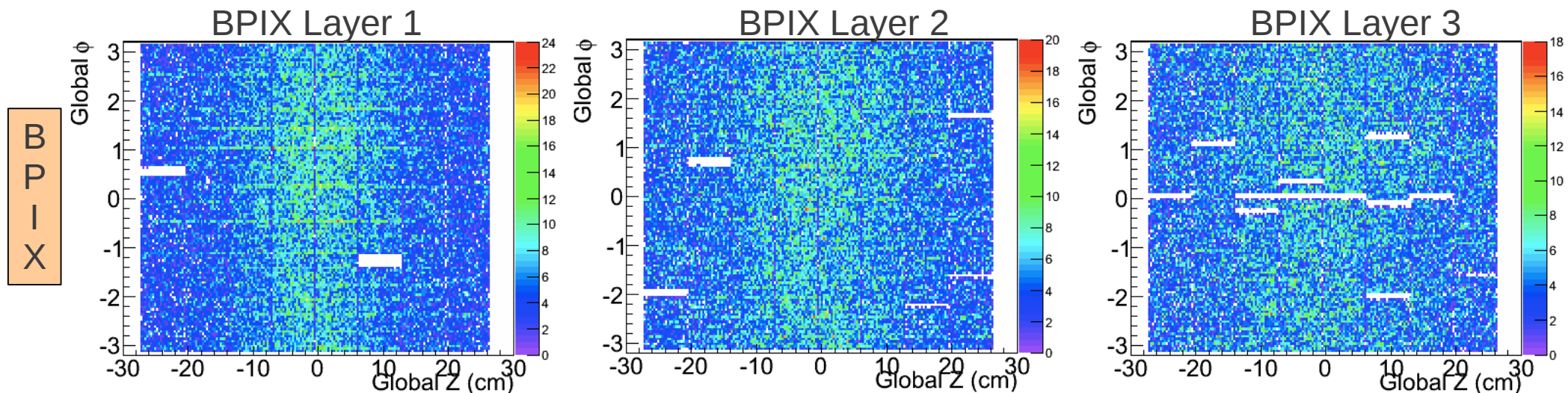
Period	Peak PU
2010	3.5
2011	18.6
2012	34.5

CMS Integrated Luminosity, pp



CMS Average Pileup, pp, 2012, $\sqrt{s} = 8$ TeV

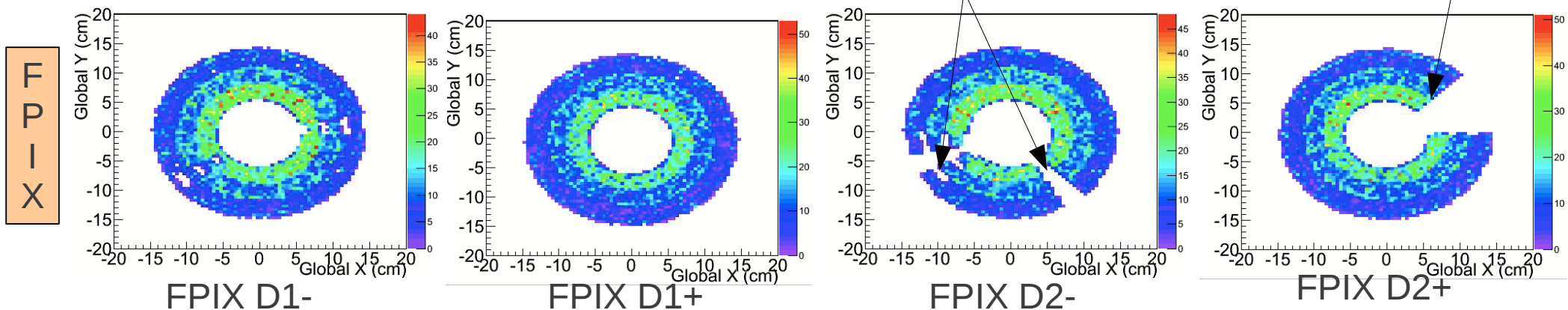




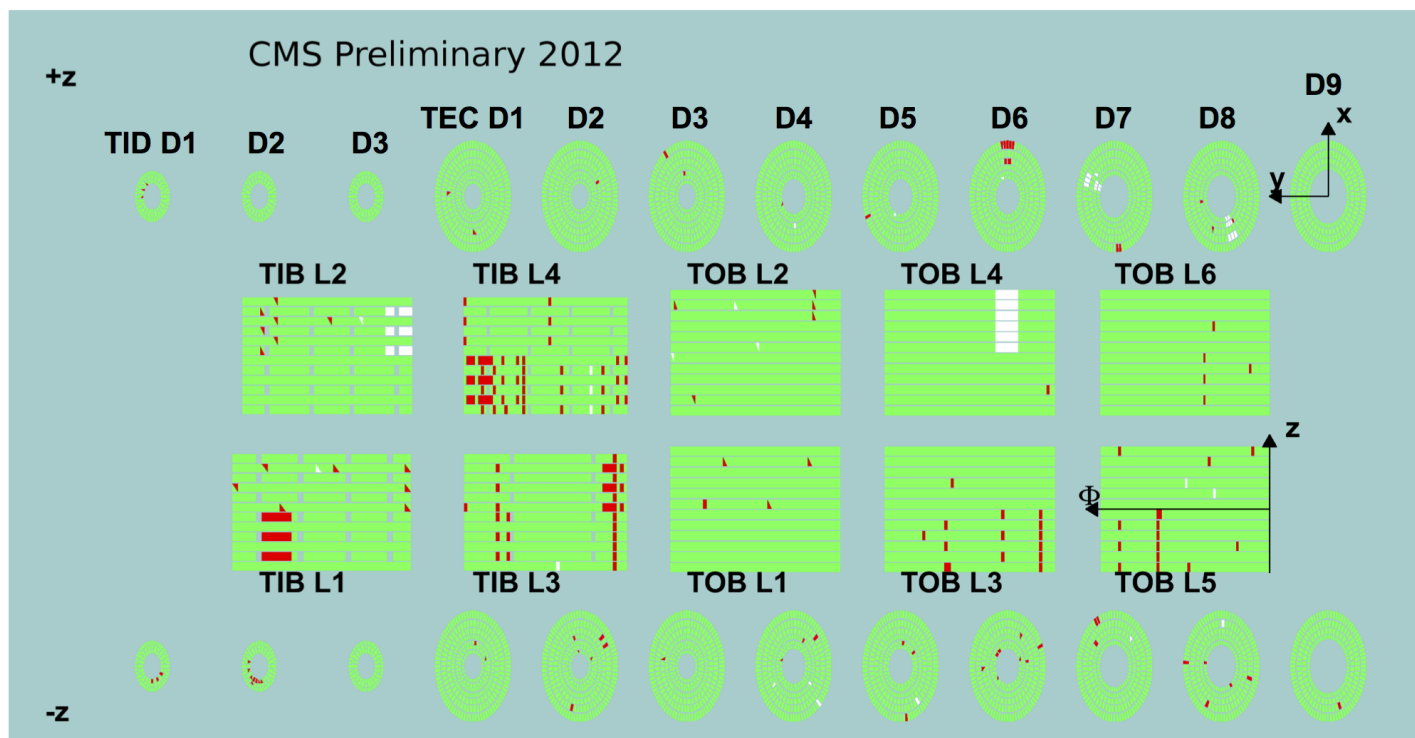
- Cluster occupancy shows the dead parts
- Channels out:
 - BPIX: ~2.3%
 - FPIX: ~7.2%

«Slow» channels :

- Long rise time in analog readout
- Pixel addresses misread
- ROCs or events miscounted if headers lost



Optical readout



- Active fraction > 97.5%
 - No/low impact on track reconstruction as many layers
- Stable :
 - 98.5% (2008) -> 97.75 % (2011)
- Can't be removed for recovery (as pixel)

Reasons for masking :

- Control ring shorts
- Control rings not functioning
- HV line shorts
- HV lines open
- Fibres, Communication and Control Units (CCU)



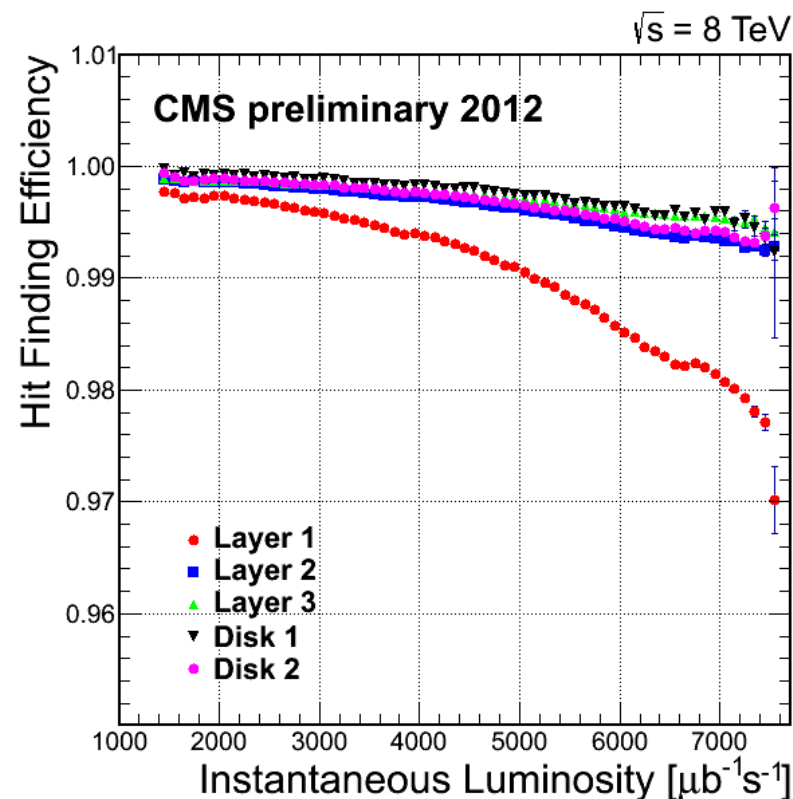
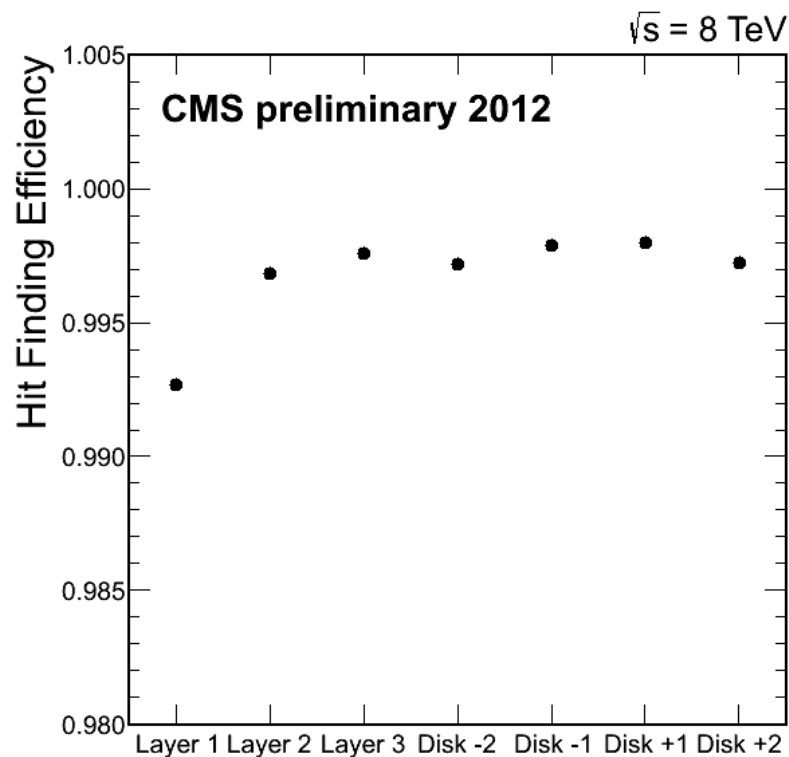
Activity on tracker during LS1



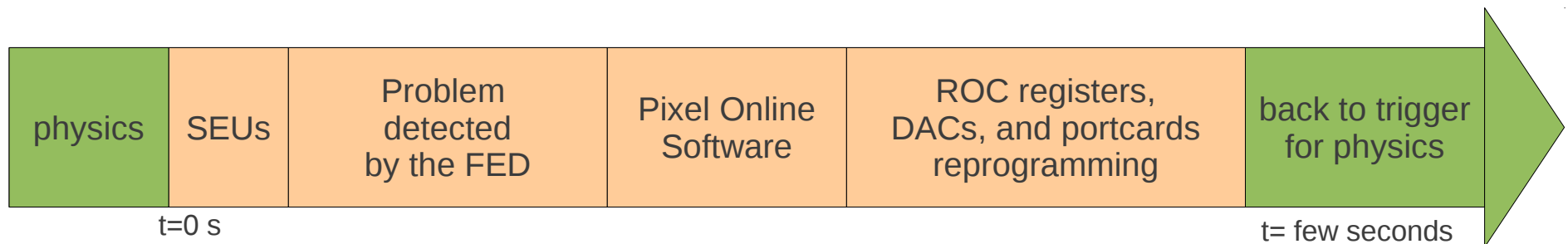
- LHC is aiming for:
 - $\sqrt{s}=13$ TeV
 - 25ns bunch spacing
 - Peak instantaneous Luminosity $\sim 1.7 \times 10^{34}/\text{cm}^2/\text{s}$
- For the Pixel:
 - Extraction and storage in a clean room
 - Broken part repair:
 - FPIX basically finished (will bring FPIX to 100% minus one chip)
 - BPIX repair ongoing (will bring BPIX to 98.9%)
 - Installation of two pixel pilot blades with modules from Phase1 upgrade
 - Better center the pixel detector during insertion in 2014
 - After installation (\sim June 2014): extensive calibration
- For the Strip:
 - No direct access to the detector: recovery of as many channels as possible
 - Lowering of the temperature: -10°C on the sensor with -20°C coolant
 - To counteract the degradation from radiation
- Maintenance and upgrade:
 - Data Acquisition system (DAQ)
 - Detector Control System (DCS)
 - Offline tools

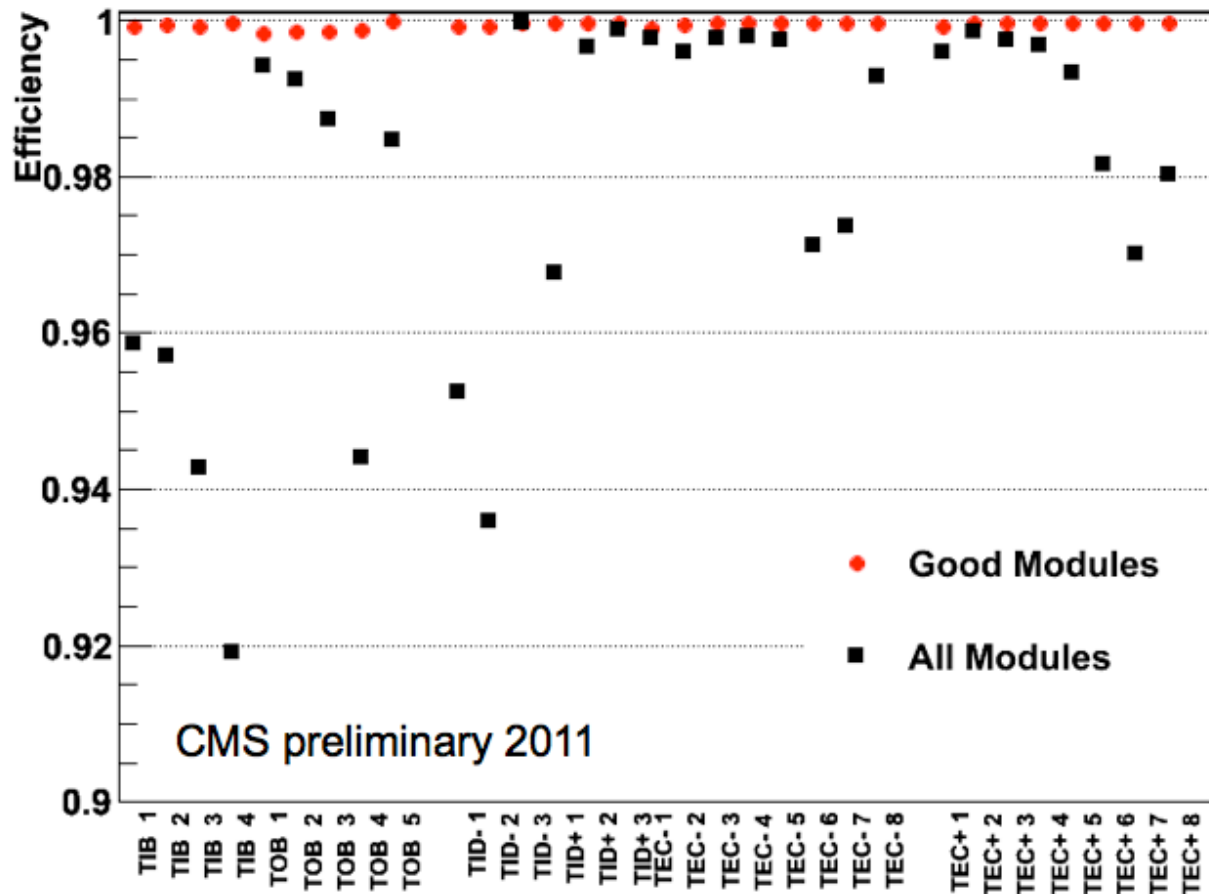
Tracker performances

- Pixel hit efficiency in general > 99%.
- Hit efficiency depends on the instantaneous luminosity due to the occupancy
 - Unavoidable inefficiency is expected due to dynamic data losses
 - pixel-by-pixel, depends on PU, L1 rate, Inst. Lumi, orbit number
 - Consists of buffer overflow, pixel over-writes, busy pixel columns and internal resets (all within the frontend readout chip)



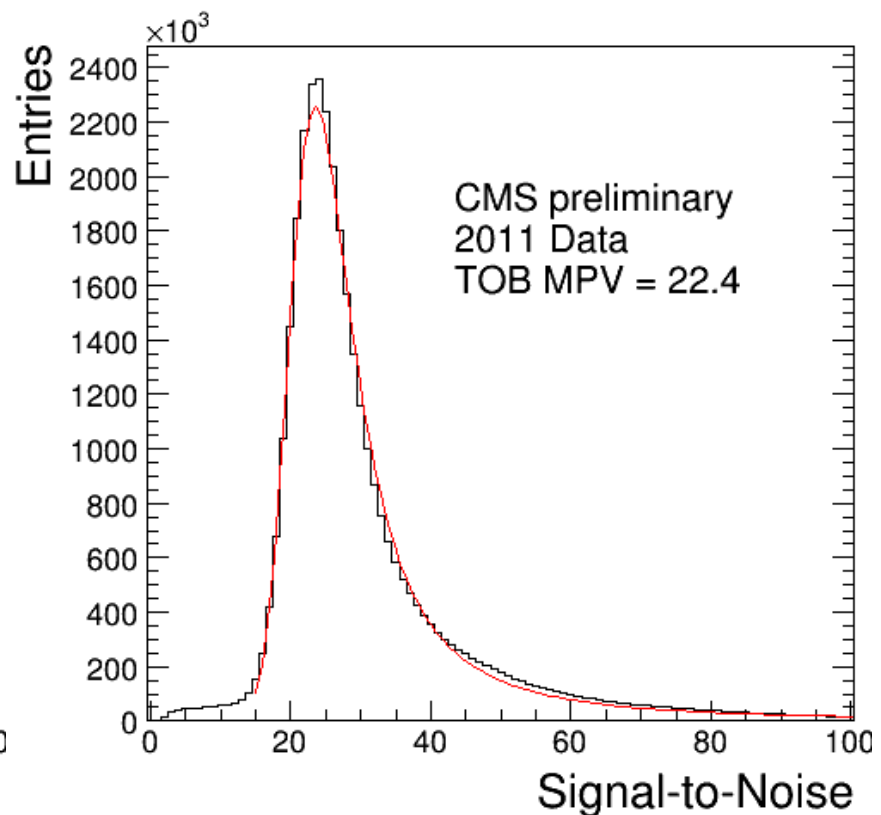
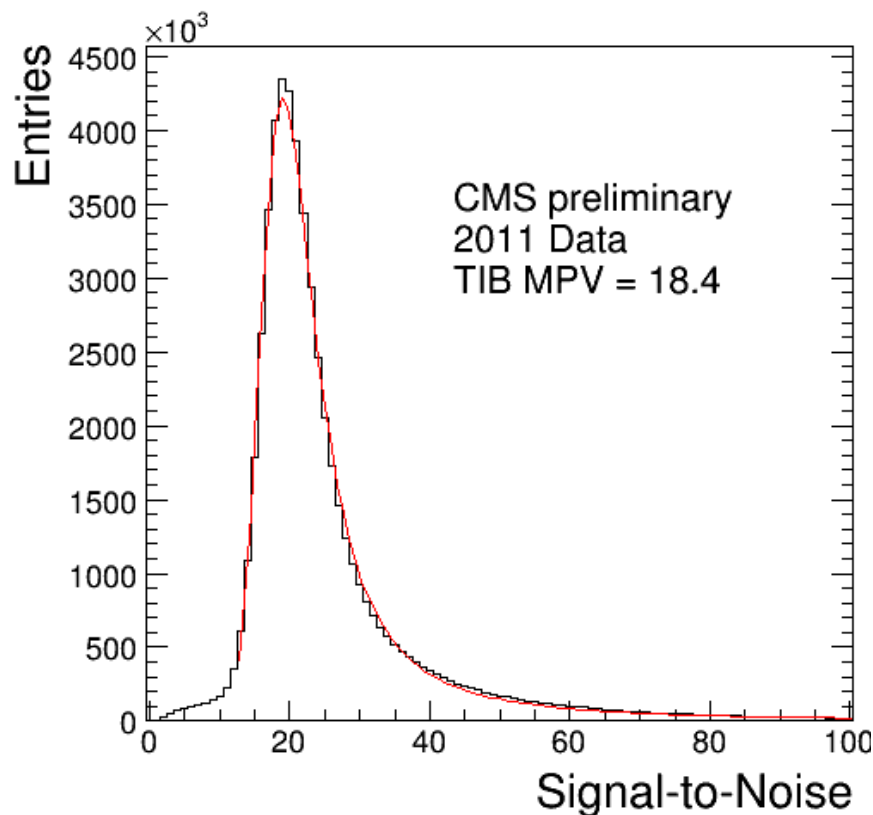
- SEU events = bit flip in the ROC or auxiliary electronics caused by ionization
- Increase with instantaneous luminosity
- Consequences :
 - interrupt data taking
 - degradation of data quality
- Does the SEU compromise data taking ?
 - ◊ No : No action needed (concern Single Pixel and single ROC i.e. <0.1%)
 - ◊ Yes : need to be fixed (concern auxiliary electronics i.e. ~1%)
 - Stop the trigger and reprogram the ROC registers, DACs, and portcards
- 1 SEU (needing treatment) every ~73 pb⁻¹ of data so ~1.5 SEUs / LHC fill

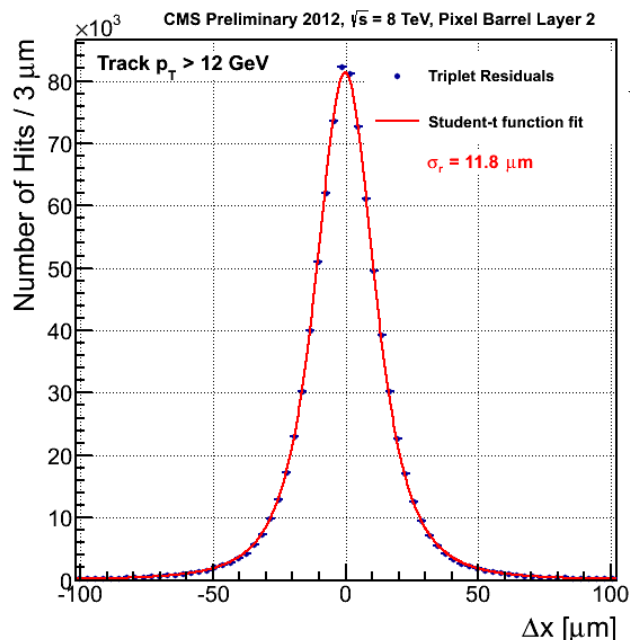




- All modules :
 - Variation down to 92 %, reflecting bad module distribution
- Good modules :
 - **> 99 % efficient** → We know very well which modules are bad

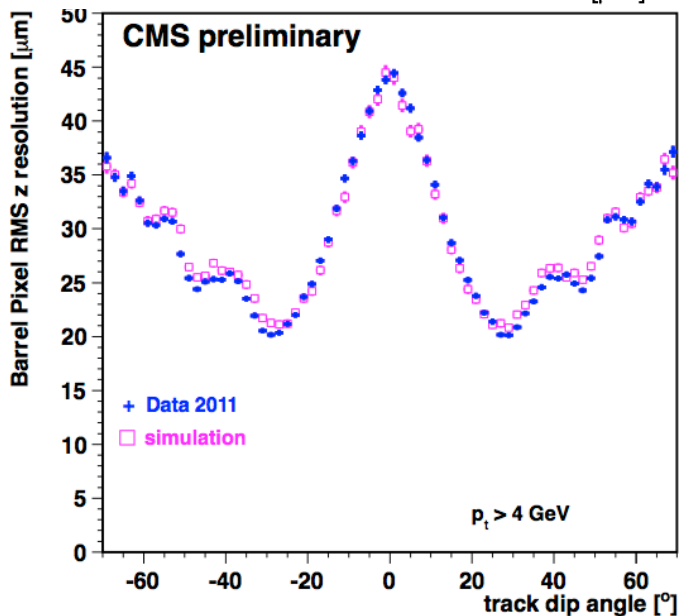
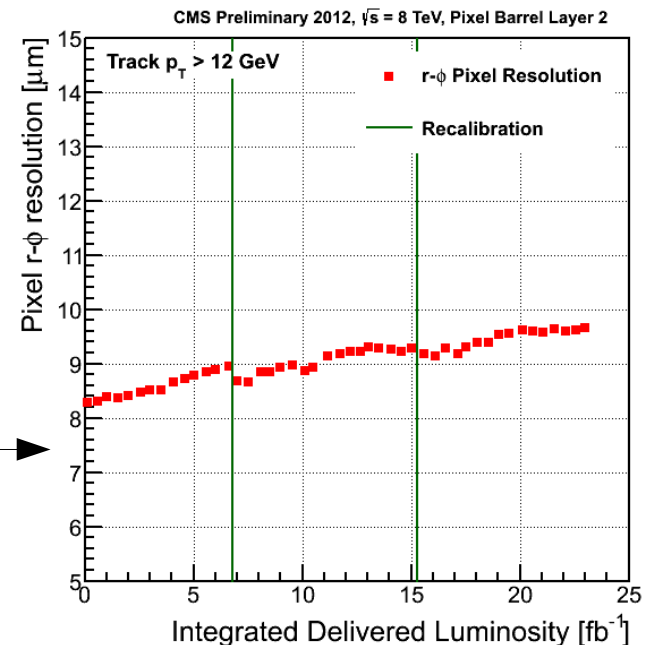
- Clusters on track only, charge corrected for track angle.
- Distributions nicely follow Landau distributions convoluted with Gaussian resolution
- Large most probable value :
 - Thin sensor (TIB) :~18
 - Thick sensor (TOB) :~22
- Consistent with values from irradiation campaigns prior to integration





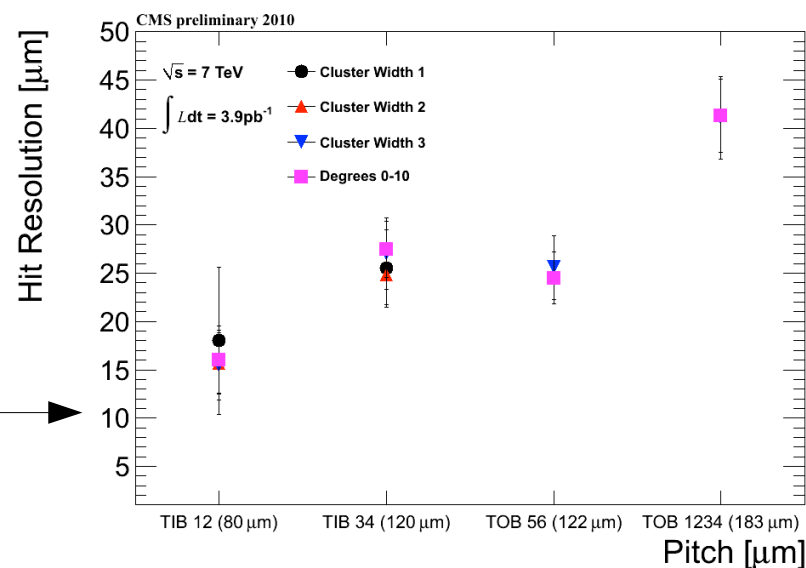
pixel triplet resolution
transverse plane

intrinsic resolution of pixel detector (barrel, layer2), from pixel triplets (2012 only)

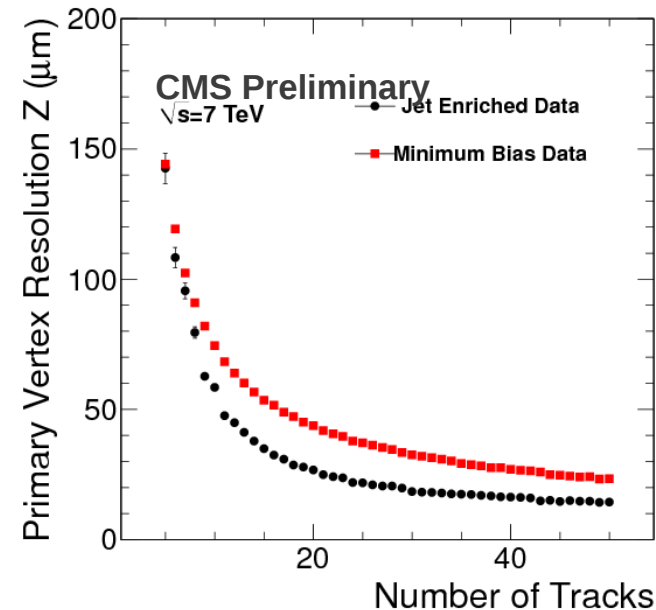
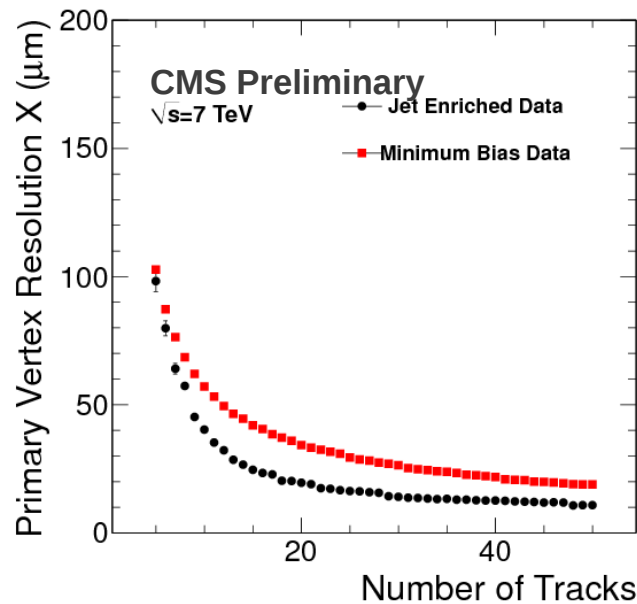
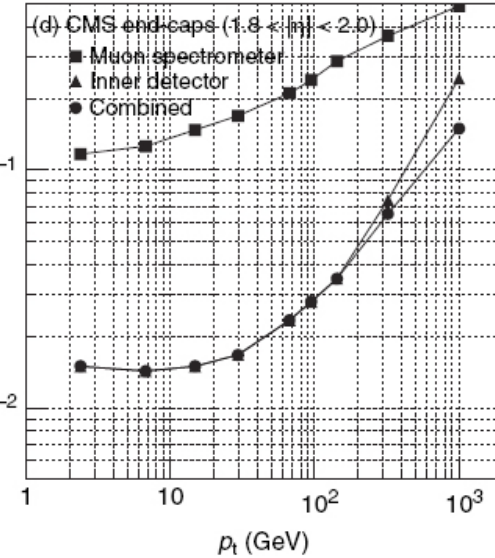
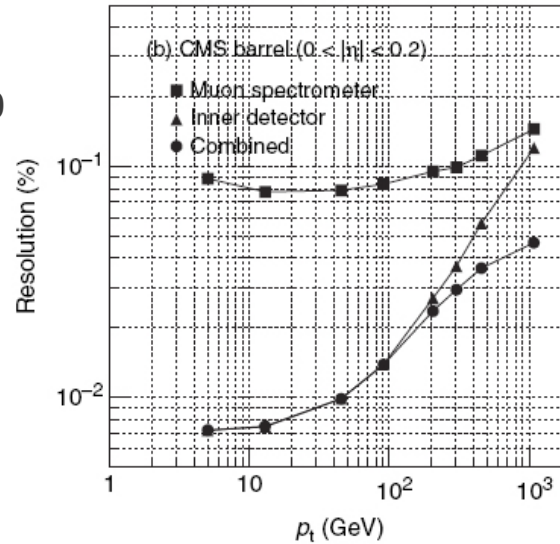


z direction resolution in barrel pixels

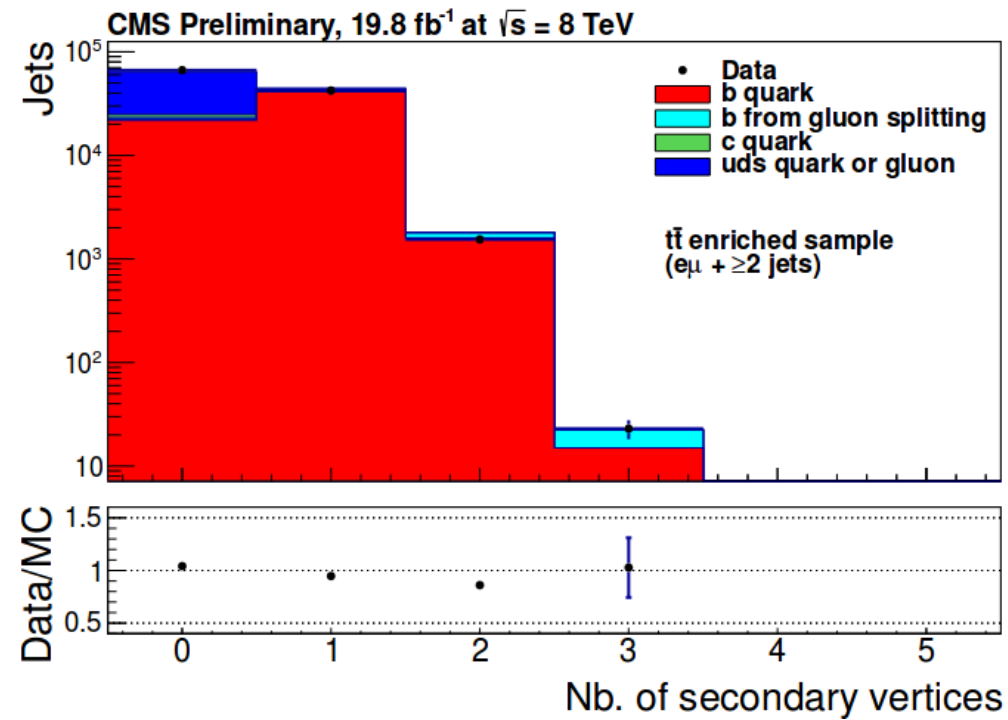
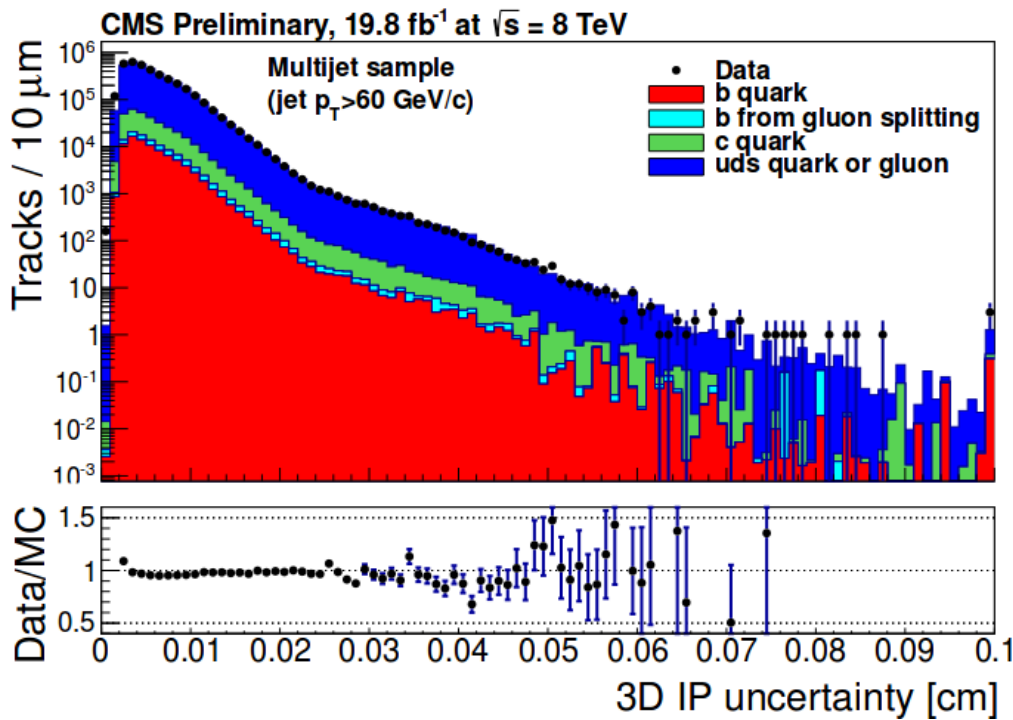
Strip Hit Resolution
vs
Subdetector pitch



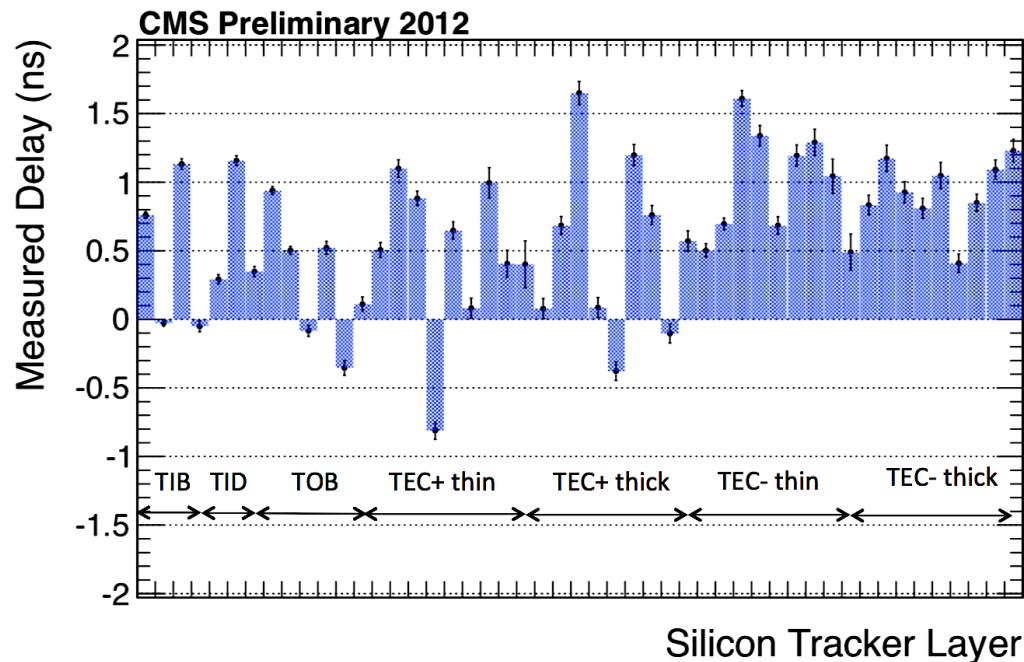
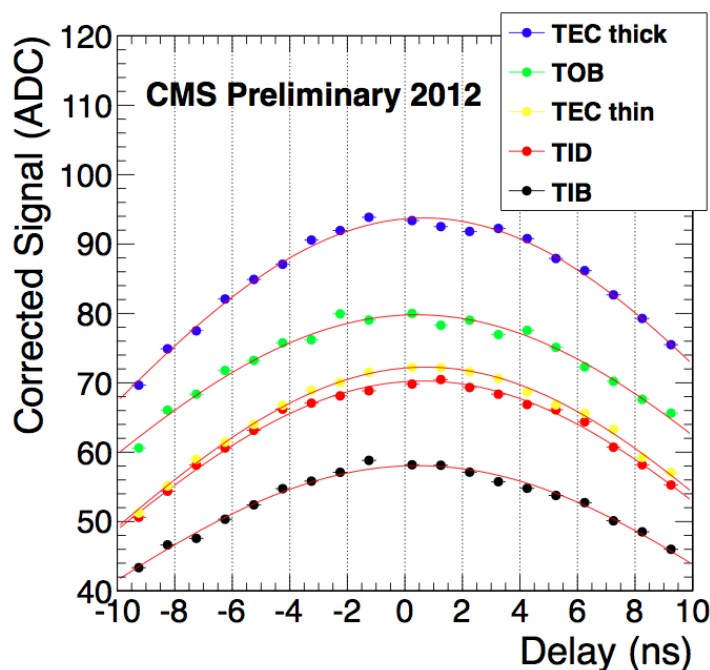
- Good hit resolution in the pixels and strip
- High hit multiplicity by tracks
- Good Momentum resolution:
 $\sigma(p_t)/p_t = 1-2\%$ for $p_t(\mu) = 100 \text{ GeV}/c$
 With the tracker only
- Combination allow to have a very good primary vertex resolution



- Thanks to a very good:
 - Hit resolution performance
 - Momentum resolution
 - Vertexing resolution
 - Precises and very discriminant inputs for the b-tagging
- Excellent description by simulation



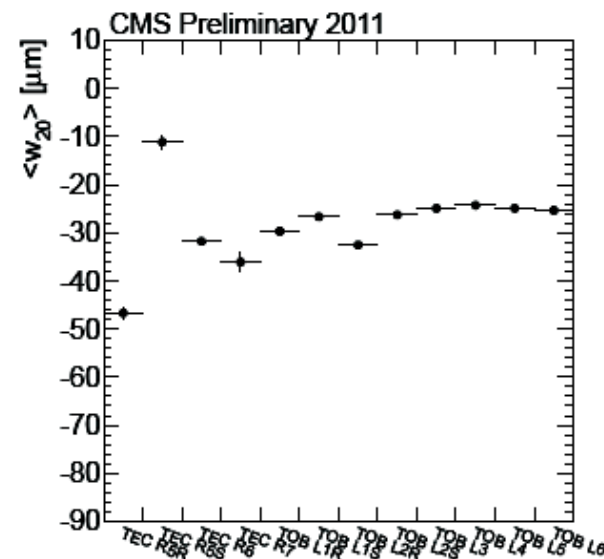
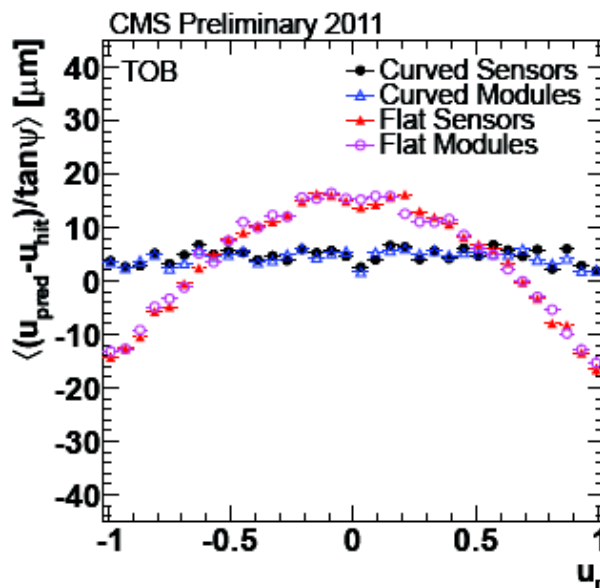
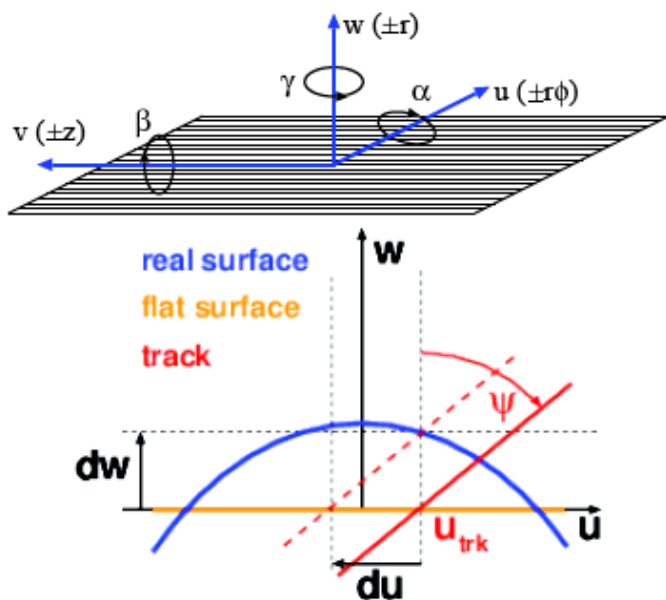
- Important for Signal-to-noise ratio if timing is off
- Efficiency suffers if far off
- Impact on occupancy due to the out-of-time pile up (OOP)
 - Minor impact at 50ns but critical at 25ns:
 - a few ns difference lead to 2→10 times more OOP
- Should be stable but can be check with a few minutes of deconvolution mode data:
 - Time delays in steps of 1.04ns (smallest possible adjustment)
 - Signal maximum must be at 0
 - Current timing is observed to be perfect and stable compared to previous years



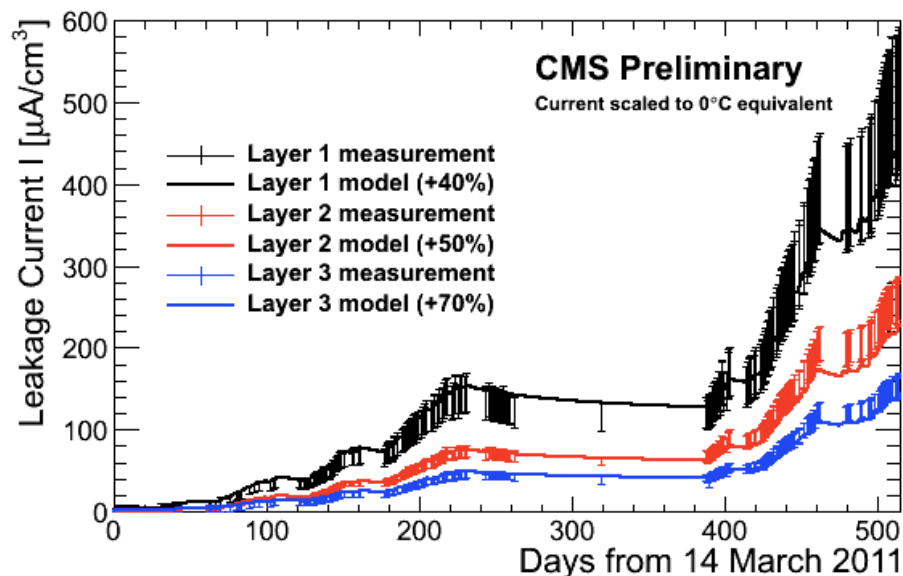
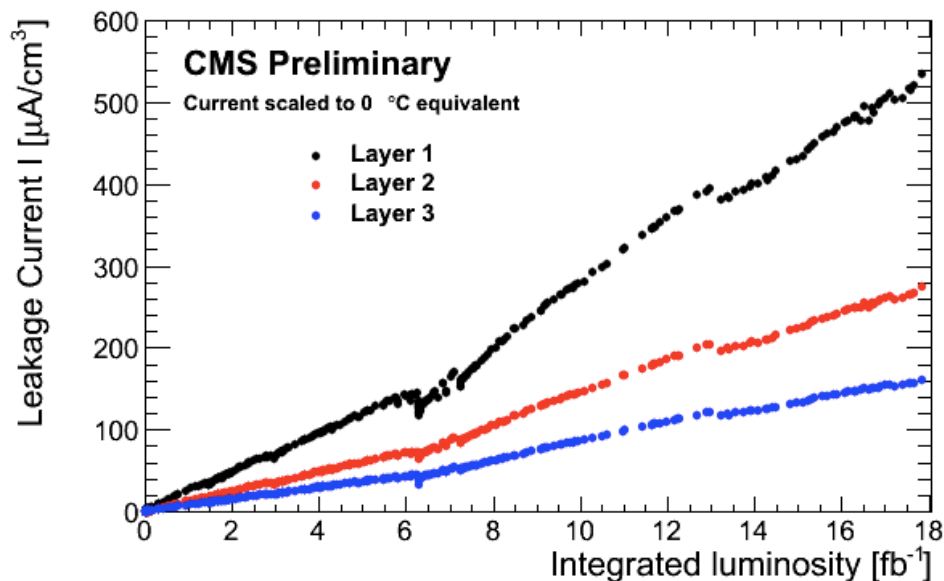
- Track-based alignment working fine (100k alignment parameters!)
 - So well mastered that we are sensitive to sensor curvature
- Single sided silicon processing
 - curved sensors (specifications: $< 100 \mu\text{m}$).
- Visible in average track angle corrected residuals:

$$\langle \Delta W \rangle = \langle (U_{trk} - U_{hit}) / \tan \psi \rangle$$

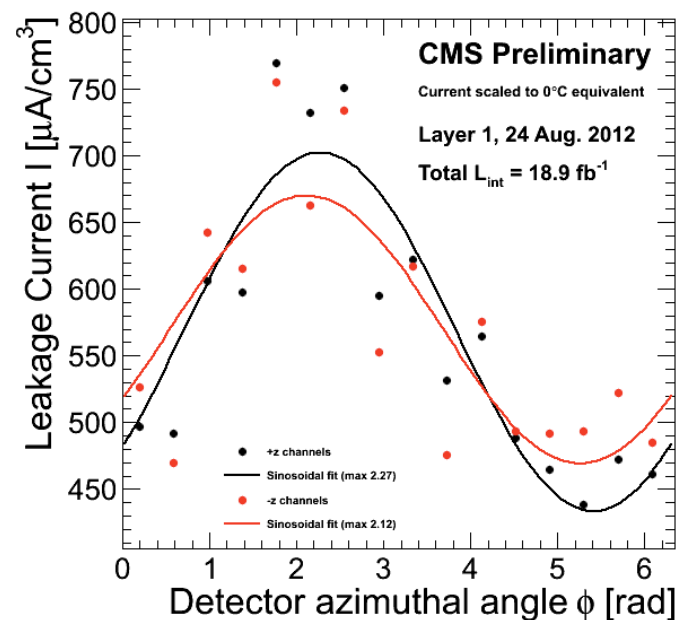
- Average amplitude in TOB: $-30 \mu\text{m}$ (with relevant RMS).
- Sensor-by-sensor values determined in alignment:
 - hit position corrections let modules appear flat (as tracking expects).



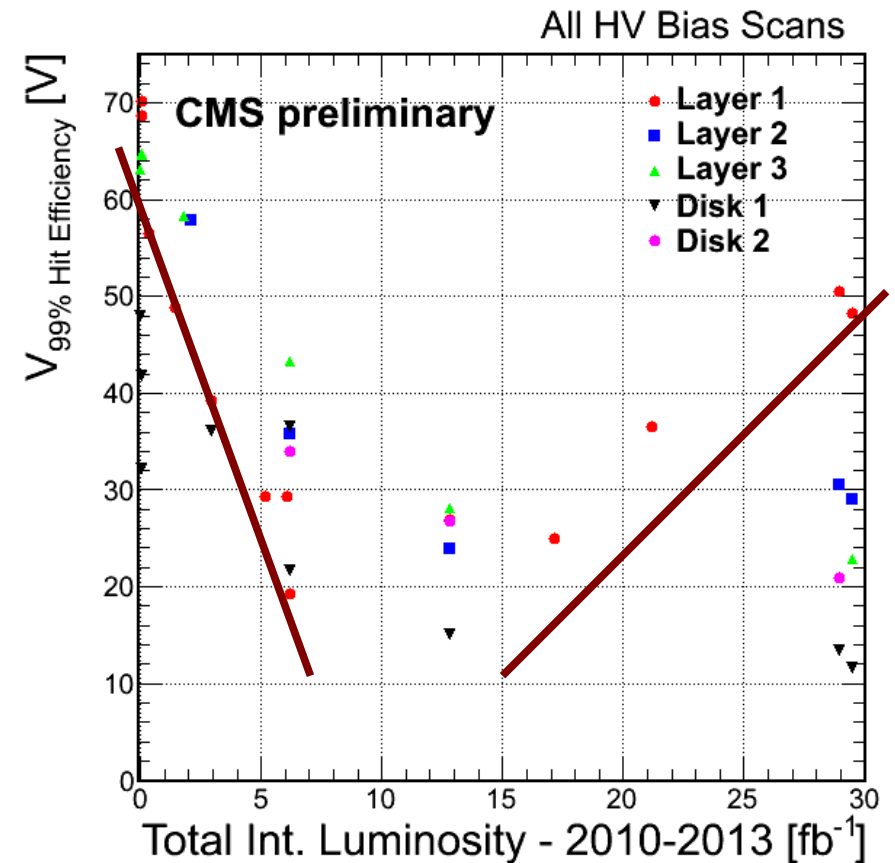
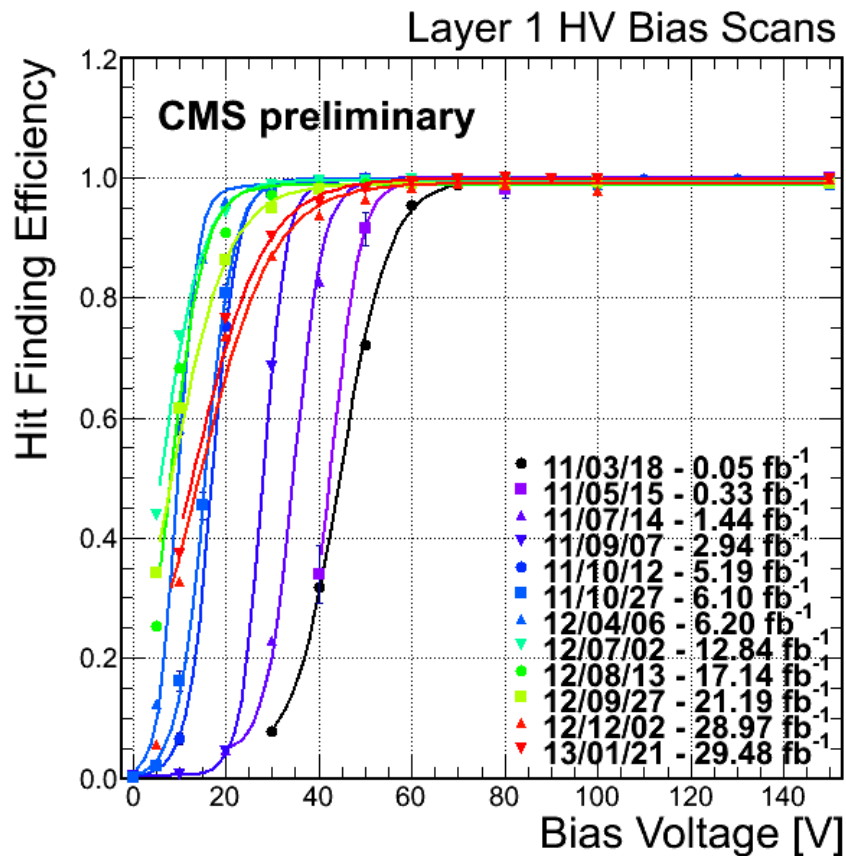
Detector evolution with integrated luminosity



- Leakage current expected to increase :
 - linearly with fluence
 - Due to bulk silicon damage
 - Partial recovery due to annealing
- Good shape agreement with models (fluka)
- Normalization low by 40-70%
- An azimuthal dependence is observed :
 - LHC Beam Spot is not at the center of Pixel Detector
 - 30% effect on potential Layer 1 lifetime
 - Expect to be fixed after LS1 and re-centering
 - Geometric issues also impact data rates → where readout issues emerge

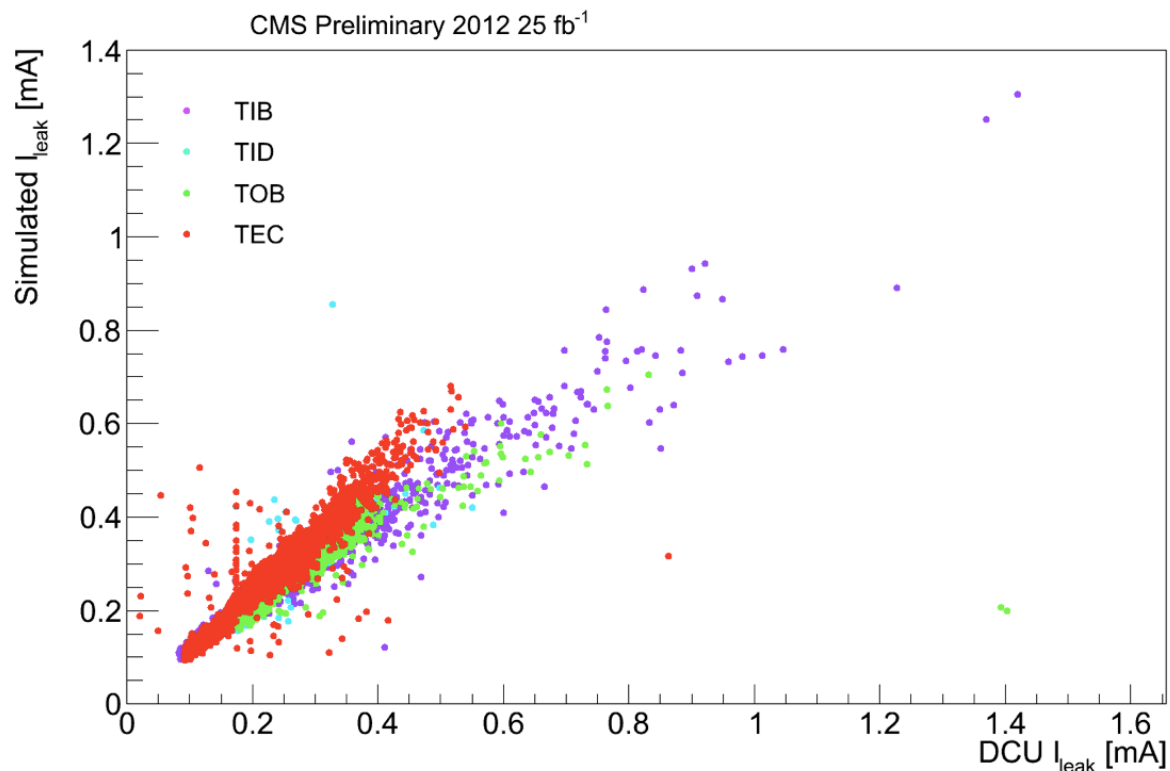


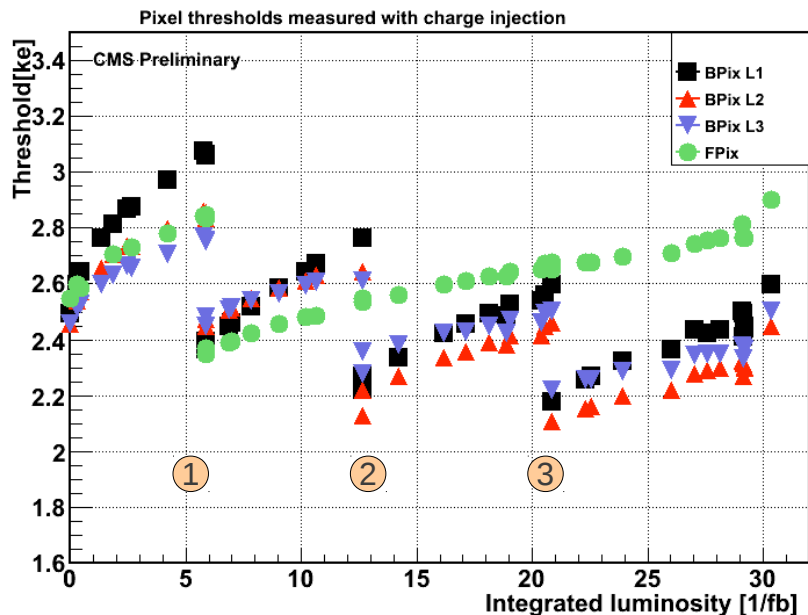
- Regular measurements of :
 - Detection efficiency
 - Charge collection efficiency vs bias voltage



- Layer 1 and layer 2 are type **inverted**.

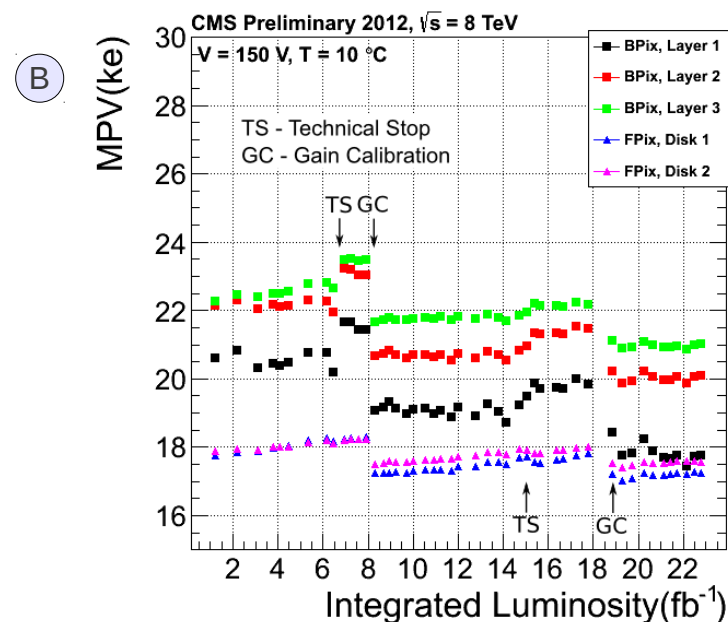
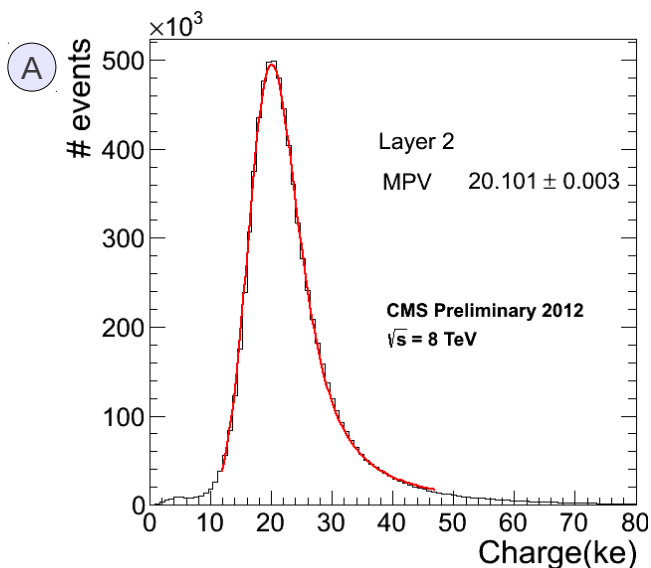
- Increase with radiation damages :
 - Give a handle to measure accumulated irradiation
- Current measured module-by-module
- Average strips measurements agree with model (fluka) within 5-20%:
 - varying over time and detector region
 - Better agreement detector regions with temperature $T < 20^{\circ}\text{C}$ (strip tracker temperature not uniform)



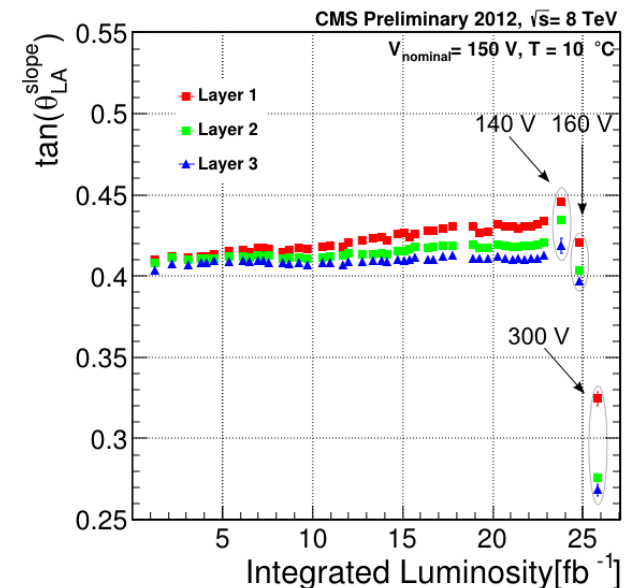
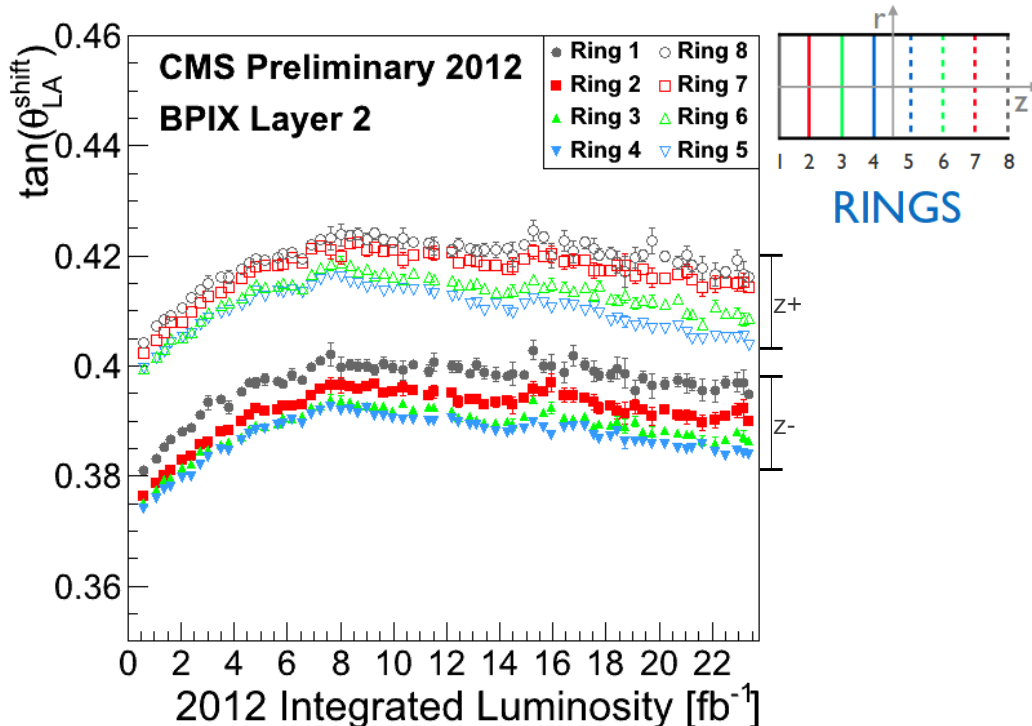
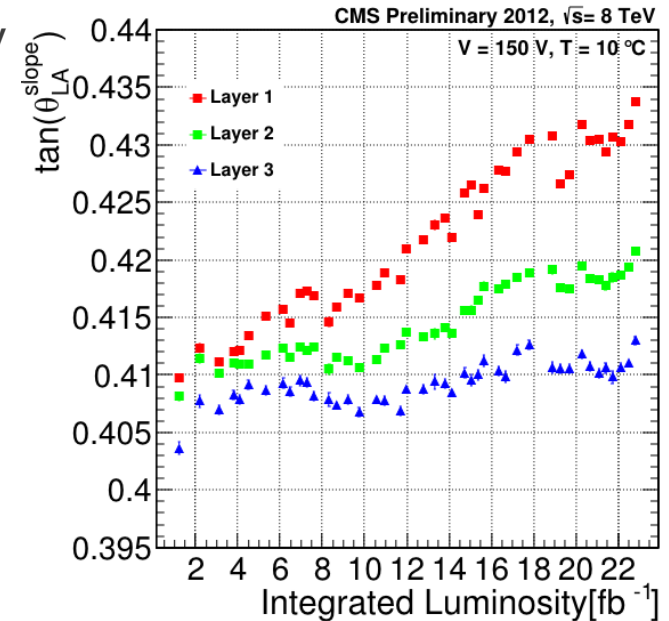


- Pixel Thresholds:
 - Depend on the integrated luminosity
 - optimized during technical stops
(End of 2011 run ①, Ju. 2012 TS ②, Sept. 2012 TS ③)

- Pixel Cluster Charge:
 - A) Distribution for each layer in pixel barrel
→ fitted to Landau distribution convoluted with Gaussian
 - B) MPV extracted from fit and plotted vs Int. Lum.



- Increase of the Lorentz angle with integrated luminosity
 - Determined using various techniques:
 - Grazing angle method
 - Alignment
 - Different impact of the irradiation on the results
- To be understood :
Offset between z+ and z- side



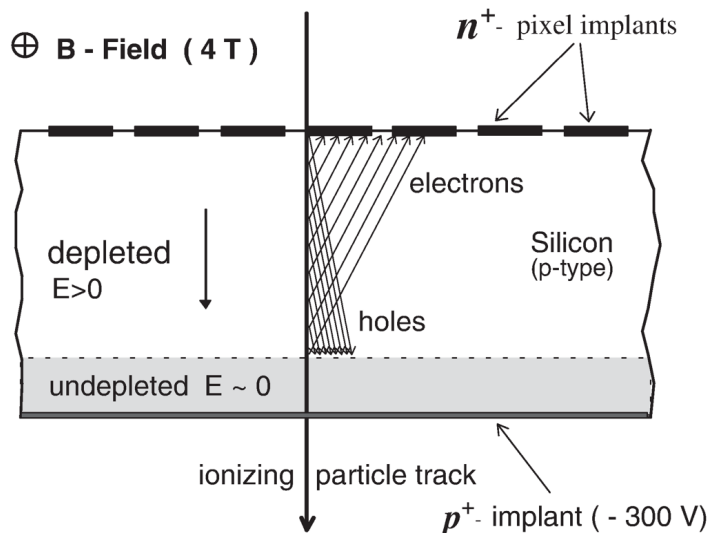


Summary

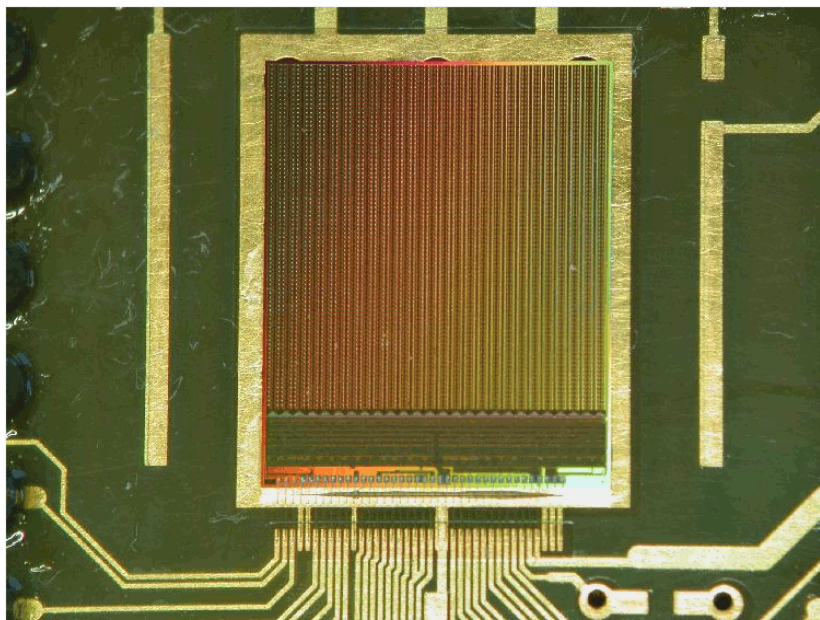


- The CMS tracker worked well during the past years of data taking
- During the data taking, some channels were lost but :
 - Mainly expected to be recovered after LS1 in the pixel
 - Not problematic in the Strip given the number of layers
- The detector has a good performance :
 - Very good signal-to-noise ratio and detection efficiency
 - In spacial, momentum and vertexing resolution
- Achieved notably because of good alignment (sensitive up to the sensor curvature) and timing
- The aging of the detector follows expectations :
 - Single event upset :
 - ◆ Rate as expected and under control
 - Irradiation :
 - Models agree in shape for both sub-detector types
(40-70 % rescaling Pixel, 5-20 % agreement for Strip depending on the temperature)
- Maintenance work during shutdown:
 - Pixel recovery (100% in FPIX, >98% in BPIX), better centering
 - Lowering of the Strip temperature to counteract radiation effect
- We are getting ready for new adventures at higher energies ...

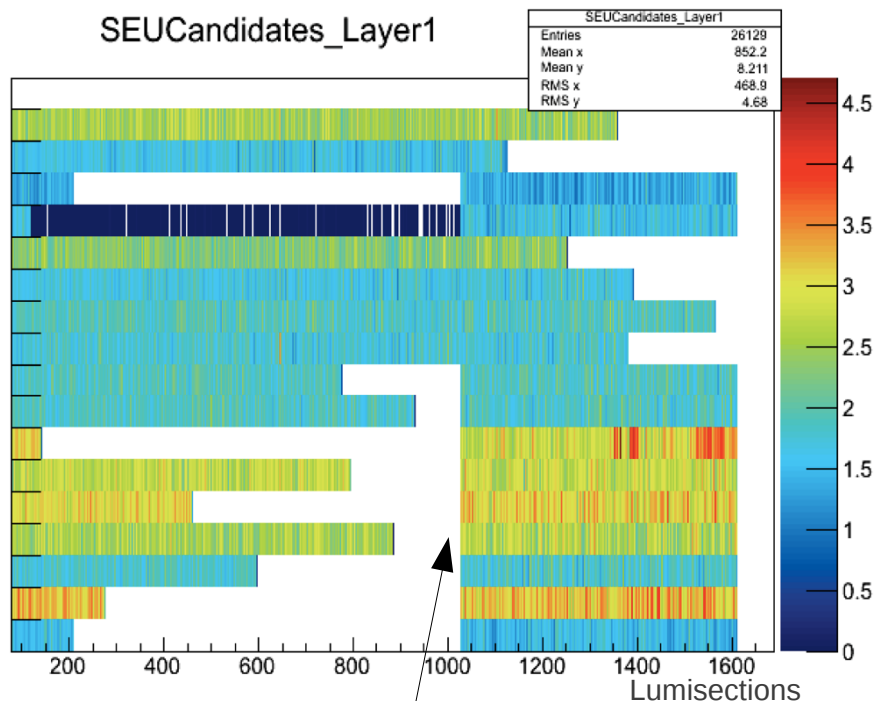
Backups



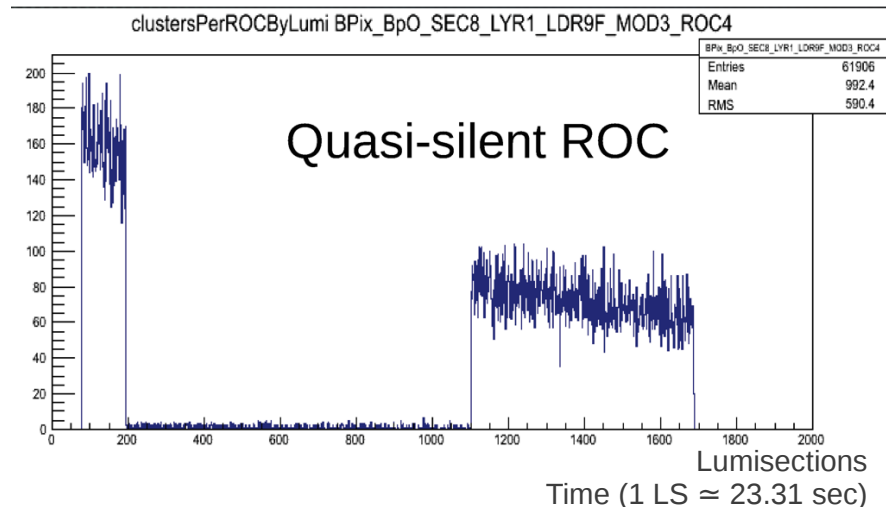
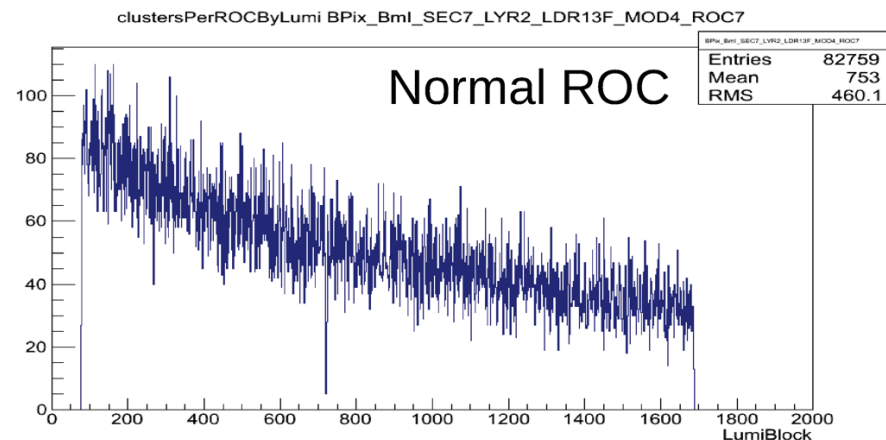
- n-in-n silicon sensor
- 52 x 80 = 4160 pixels by sensor
- Pixel size: 100 μ m x 150 μ m
- ReadOut Chip (ROC) designed by PSI and manufactured by IBM
- Automatic zero-suppression;
- 26 DACs to regulate settings, each pixel has a 4-bit DAC for fine adjustments (trimming)
- Double-column drain architecture:
 - Hits stored in a buffer until trigger confirmation
 - Single 25ns-wide bunch-crossing readout

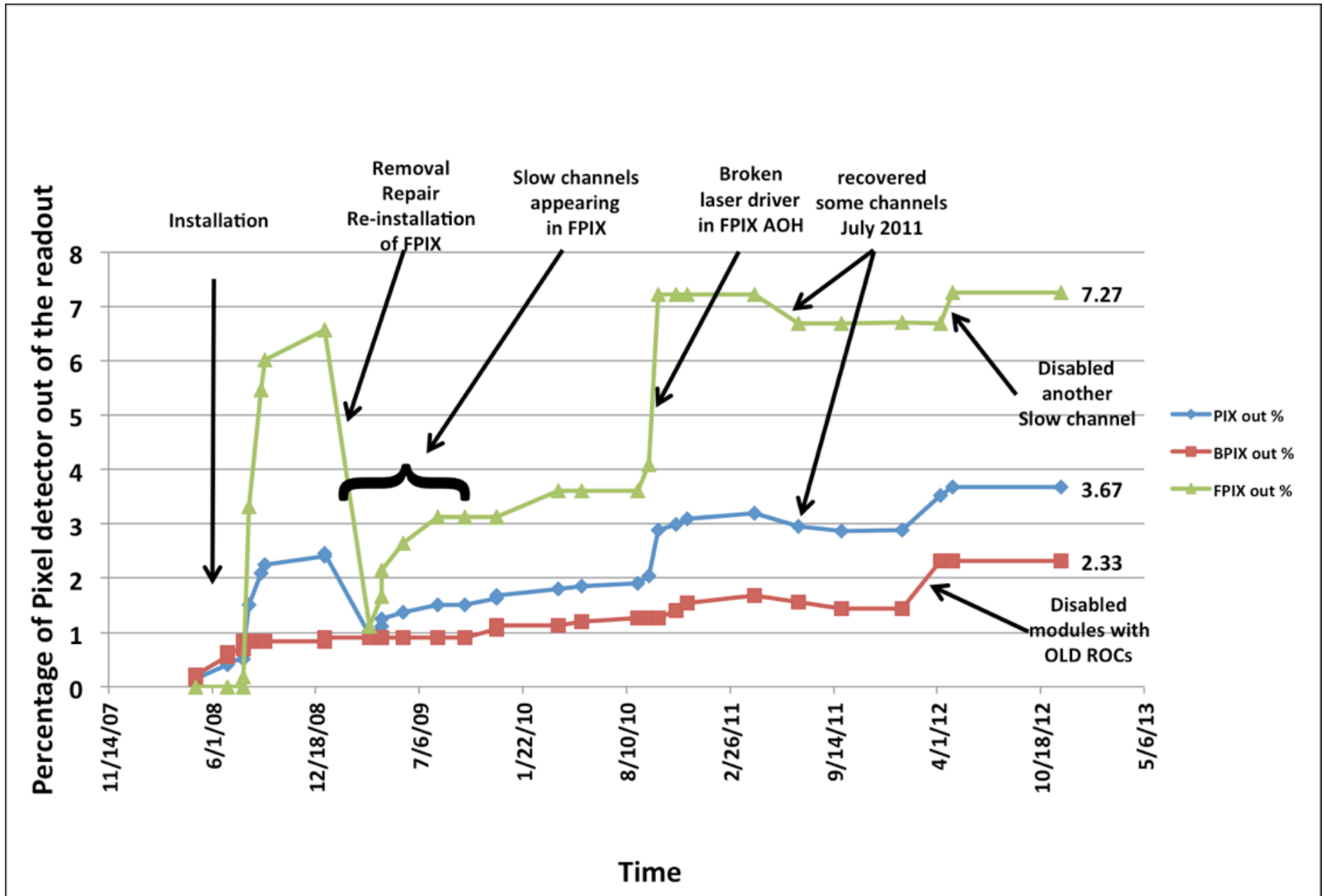


- Two mechanisms to detect SEU
 - monitoring the off channels
 - searching the Out of Sync (OOS) errors

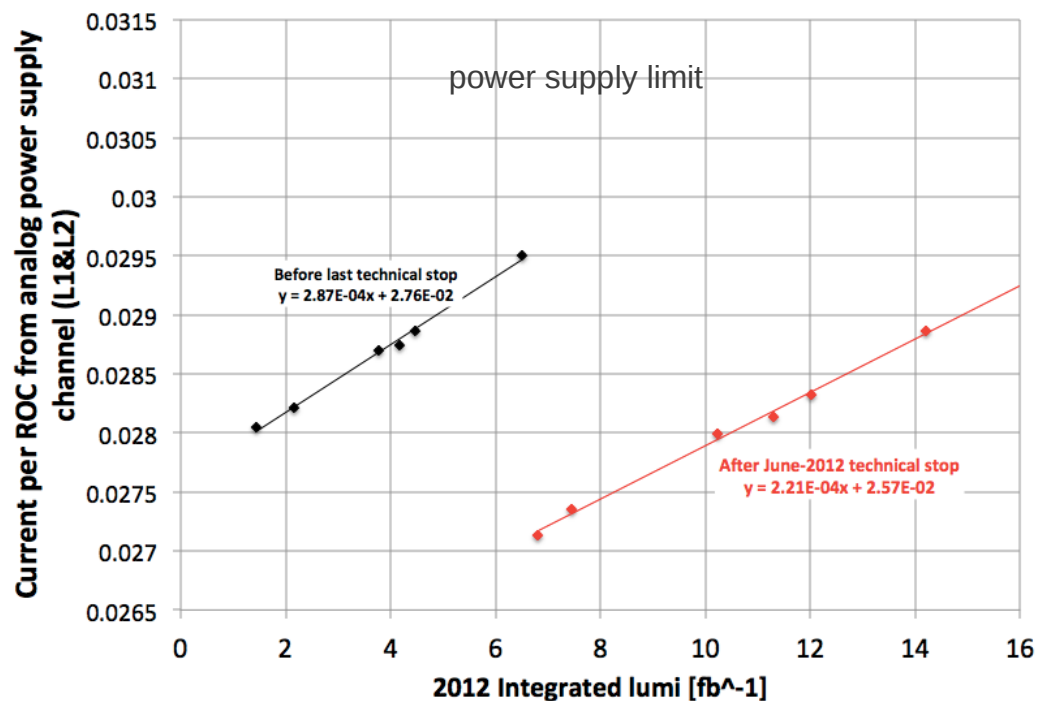


SEU recovery

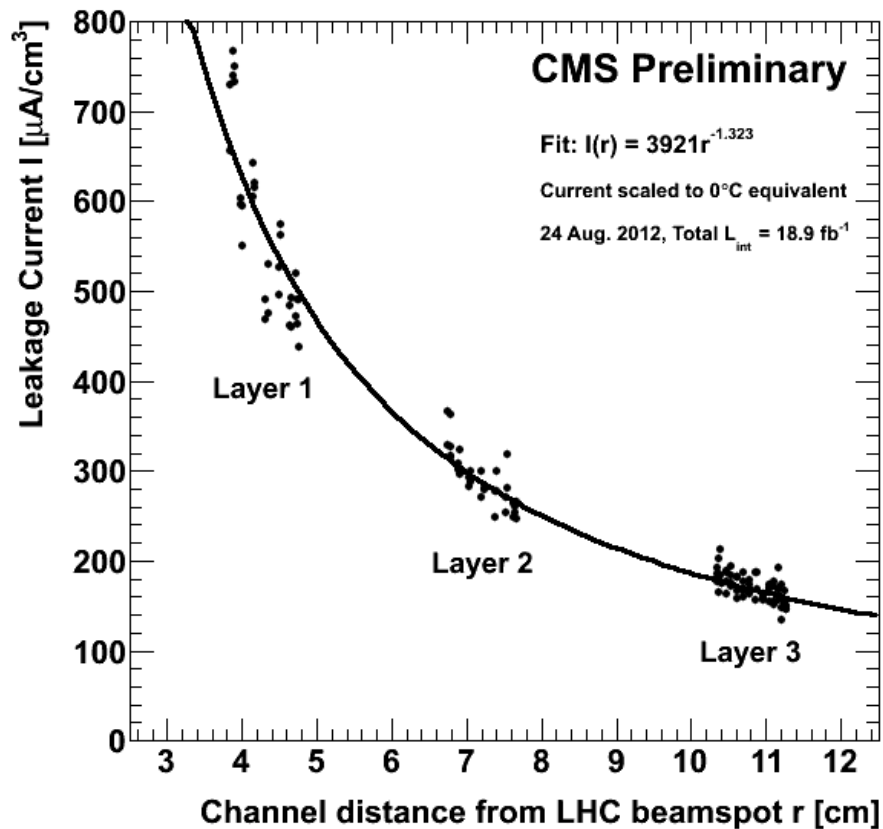




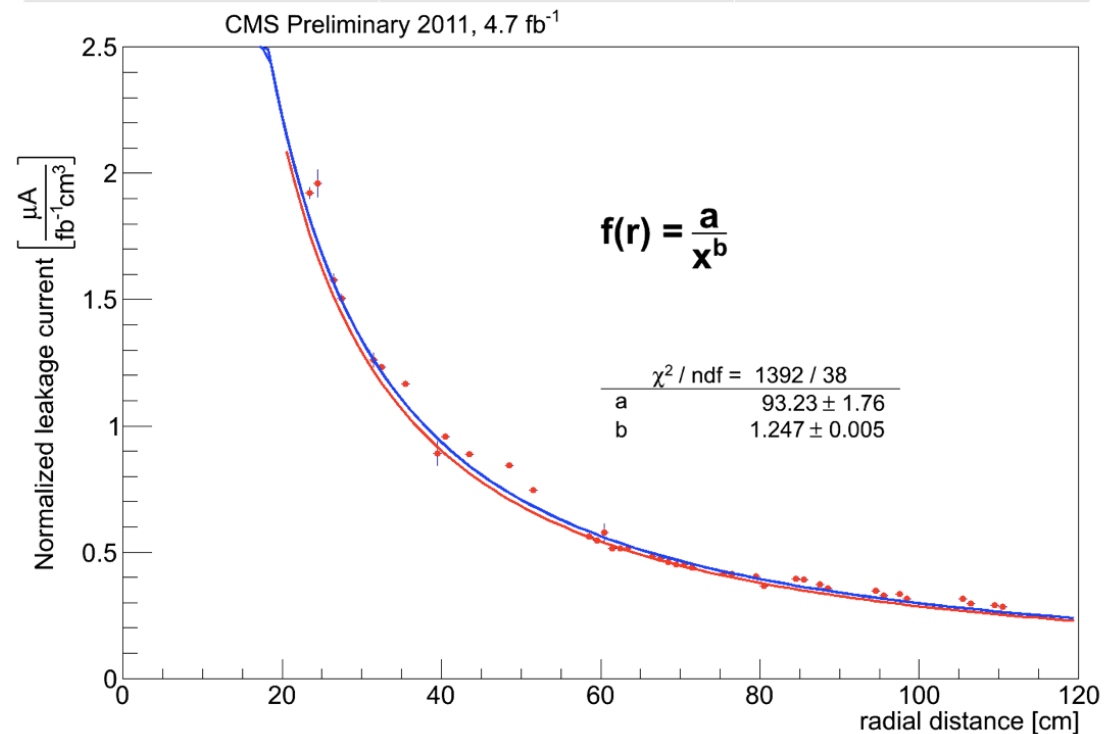
- ROC Analog circuit current increases linearly with radiation damage
 - Slower preamplifier rise time
 - Higher pixel threshold
- Biggest operational concern: power
 - supply current limit per channel
 - Limit 6 A, operate ~5.5 A
- Fixed by recalibration
- Possible mechanism
 - change in DAC setting meaning
 - caused by bulk damage in diode used for reference voltage

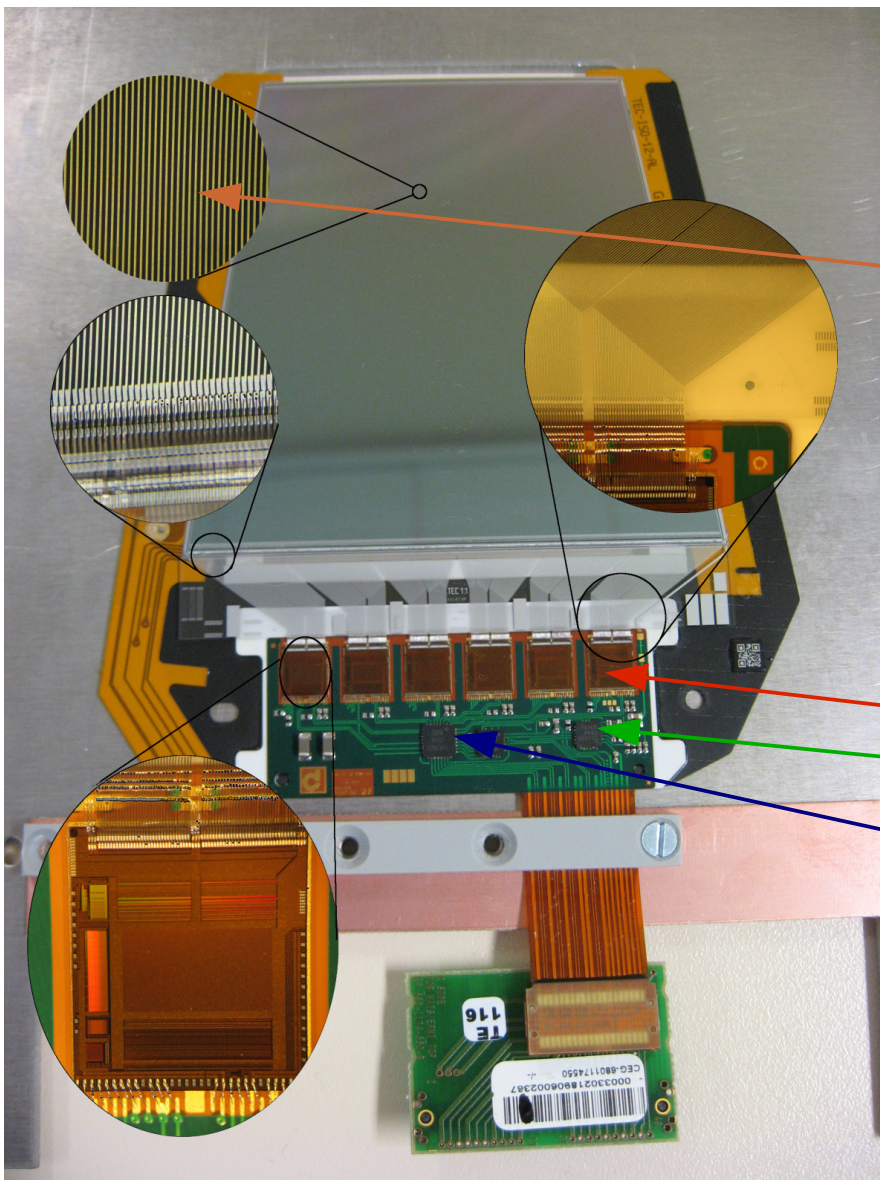


- Pixels: beam spot offset allows measurements at different radii
- Independent leakage current fits give good agreement in radial dependence
- Fitting function: a/x^b



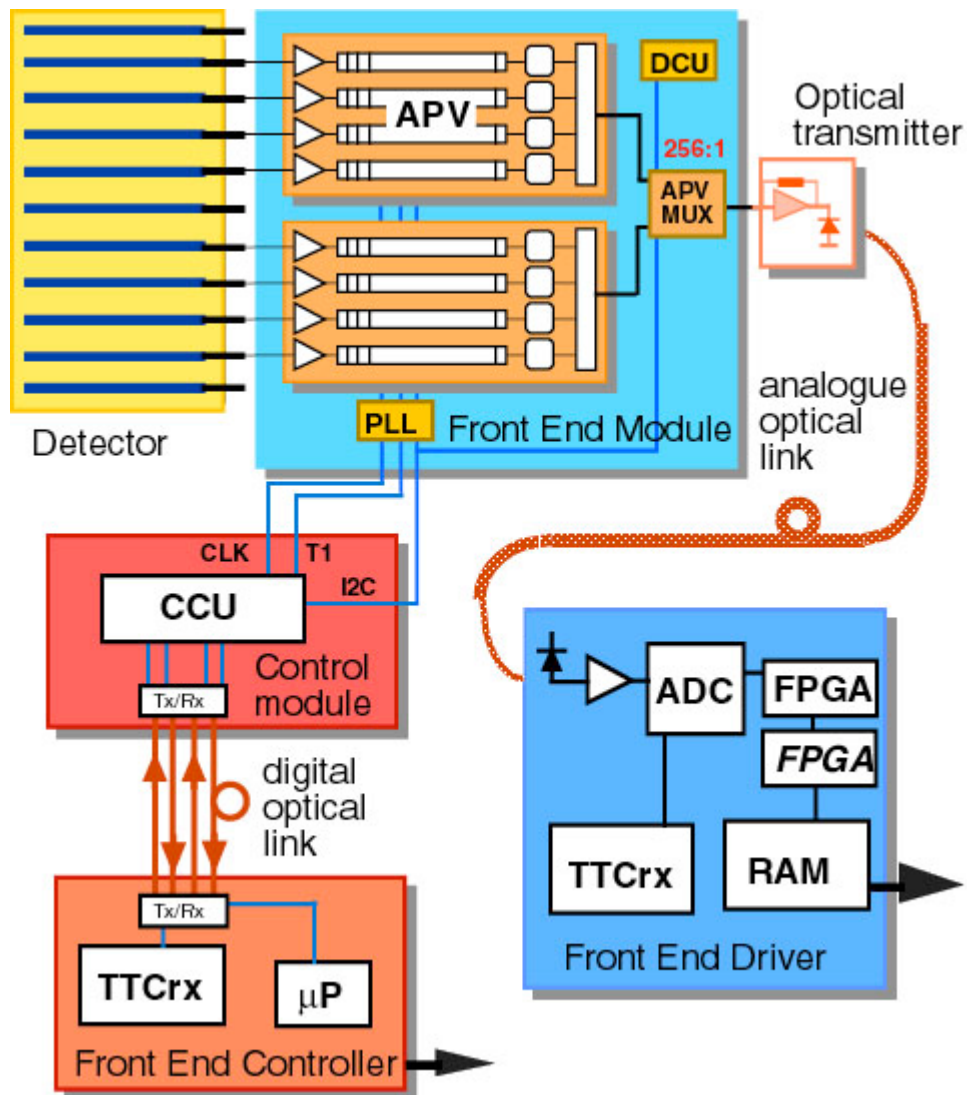
fitted parameter	pixels (18.9 fb ⁻¹)	strips (4.7 fb ⁻¹)
a	3921 ± 5	93.23 ± 1.76
b	1.3228 ± 0.0008	1.247 ± 0.005



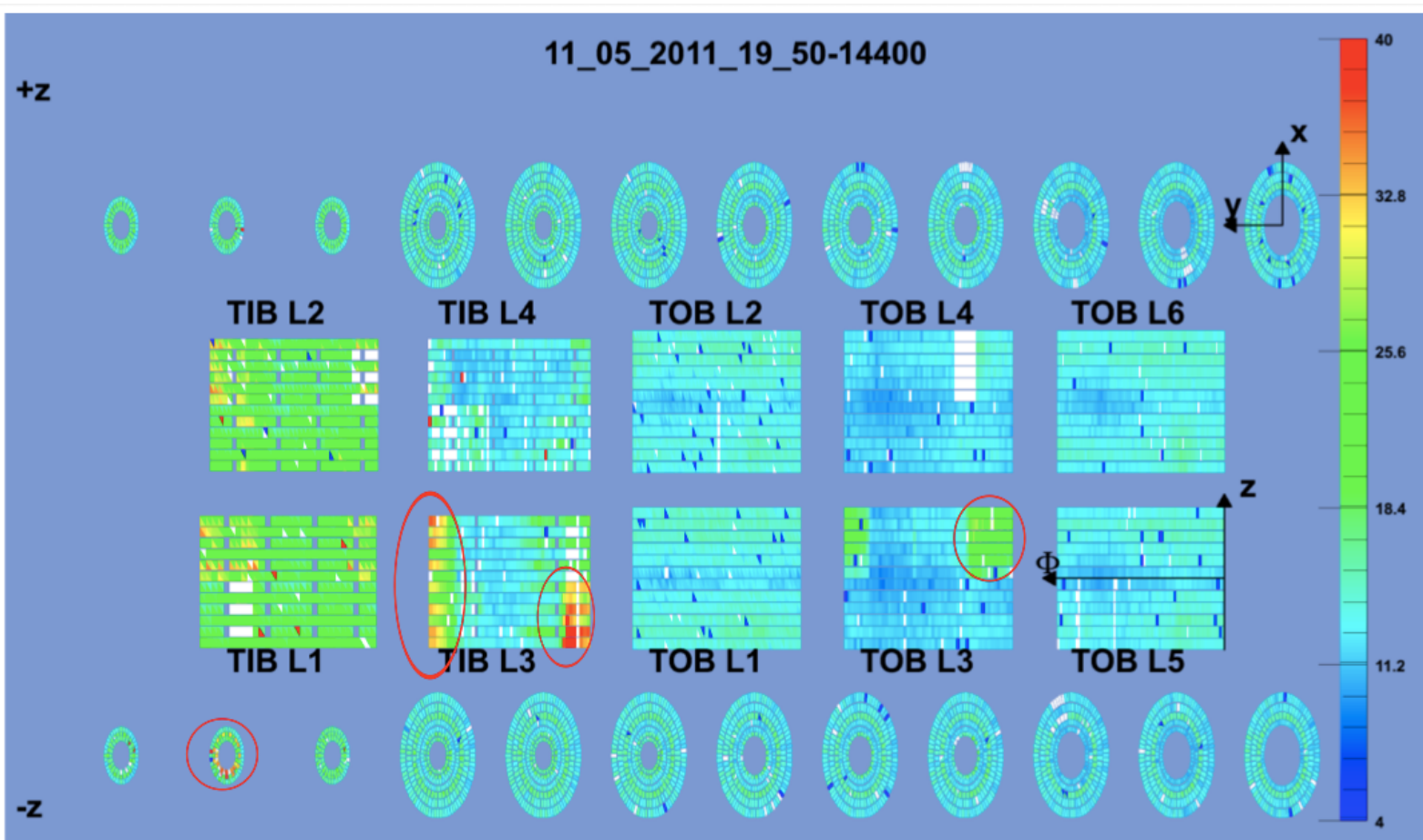


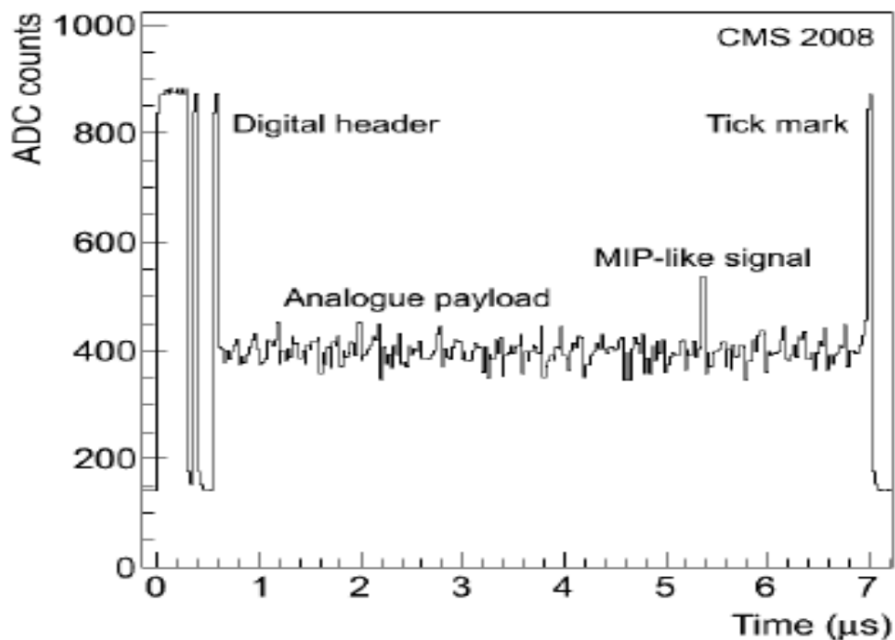
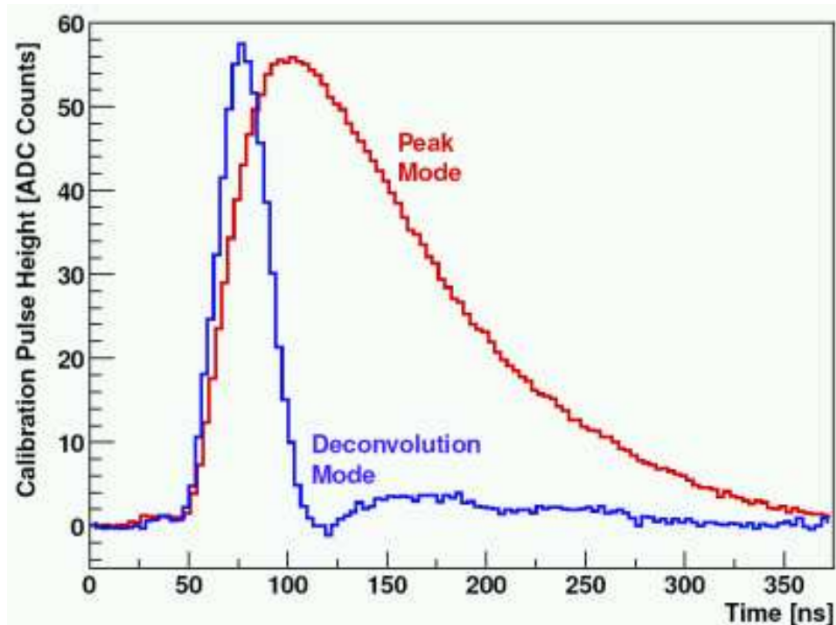
- Sensor
 - p⁺ implant in n-type silicon bulk
 - 512 or 768 **strips**
 - strip pitch $p=80-205$ m.
 - $w/p = 0:25$ (w: p⁺ implant width).
 - AC-coupled readout.

- Electronics on Hybrid
 - 4 or 6 **APV** readout chips.
 - **DCU**: leakage current, temperature, .
 - Multiplexed on 2 or 3 readout lines by **MUX**.



- Pixel operates at 17°C in 2011 and 10°C in 2012
- Not all the strip detector regions have direct cooling

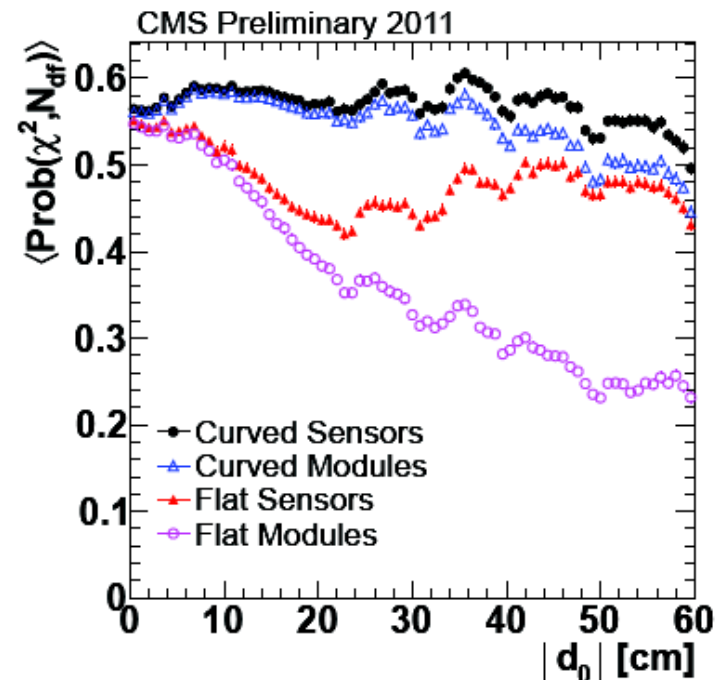
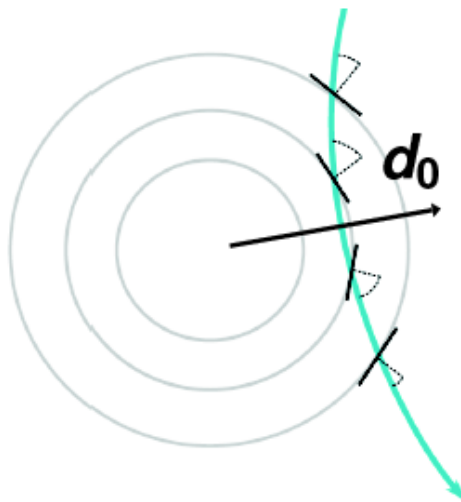
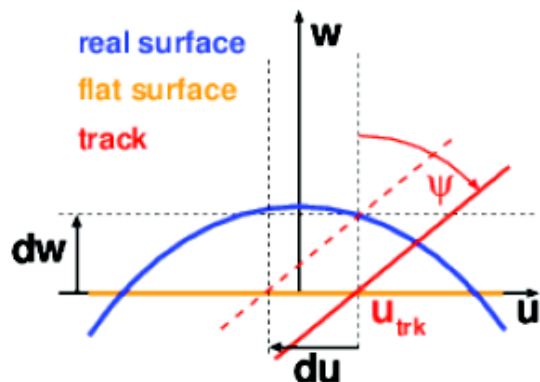




- APV Chip
 - Analog readout every 25 ns.
 - 192 cell pipeline
 - Peak mode (signal height p),
 - ♦ CR-RC circuit (50 ns),
 - ♦ low noise,
 - ♦ robust for time misalignment
 - Deconvolution mode,
 - ♦ signal at t is weighted mean:

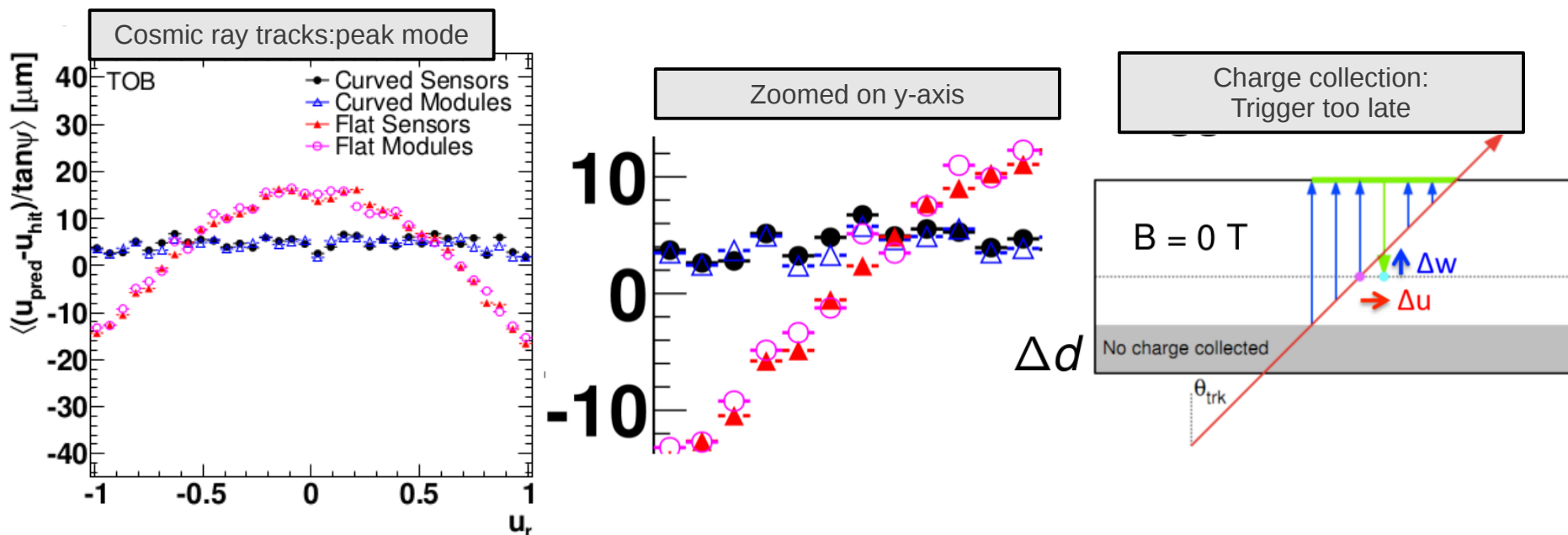
$$d_t = w_3 p_{t-2} + w_2 p_{t-1} + w_1 p_t$$
 - ♦ shorter signal,
 - ♦ higher noise.

- Signal Frame: 2 APVs Interleaved
 - Headers and tick marks frame
 - 2 x 128 analog signals
 - Send on external trigger



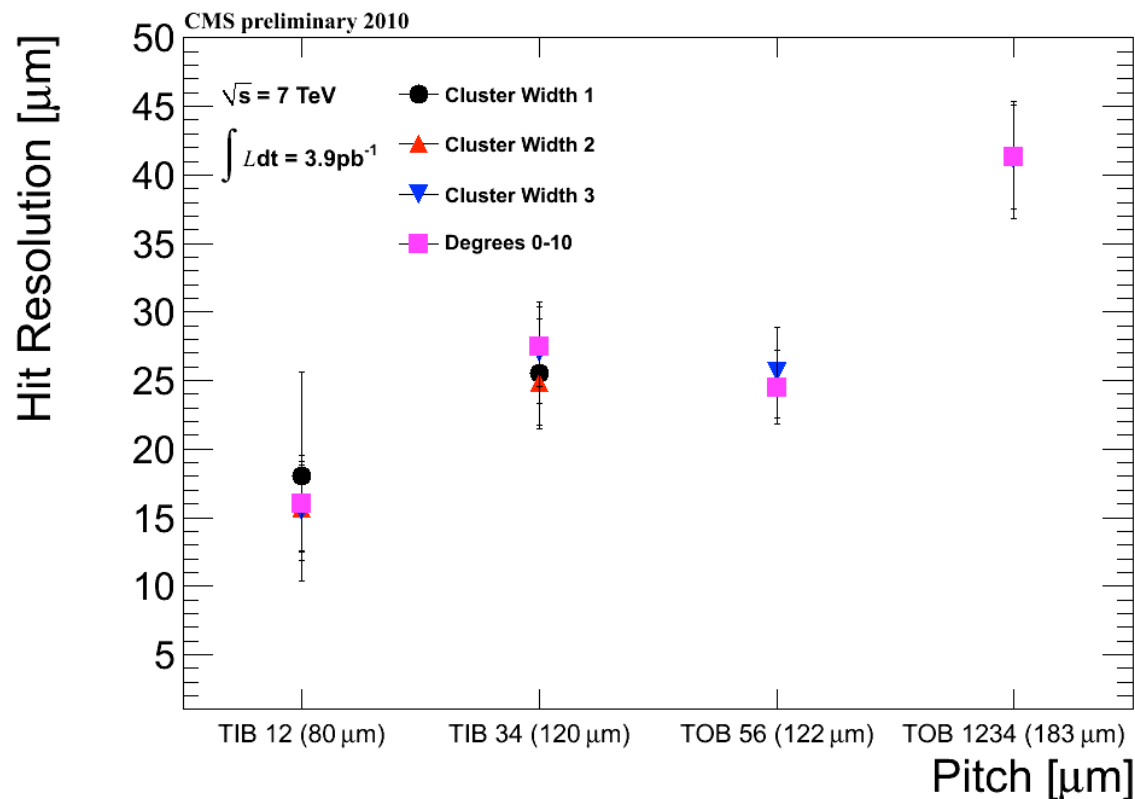
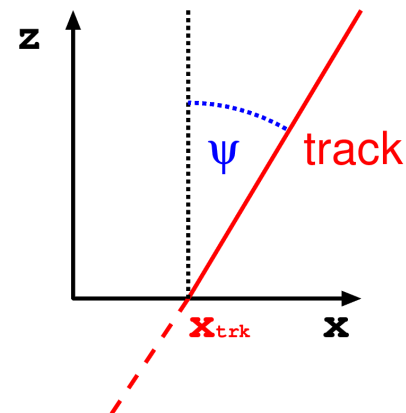
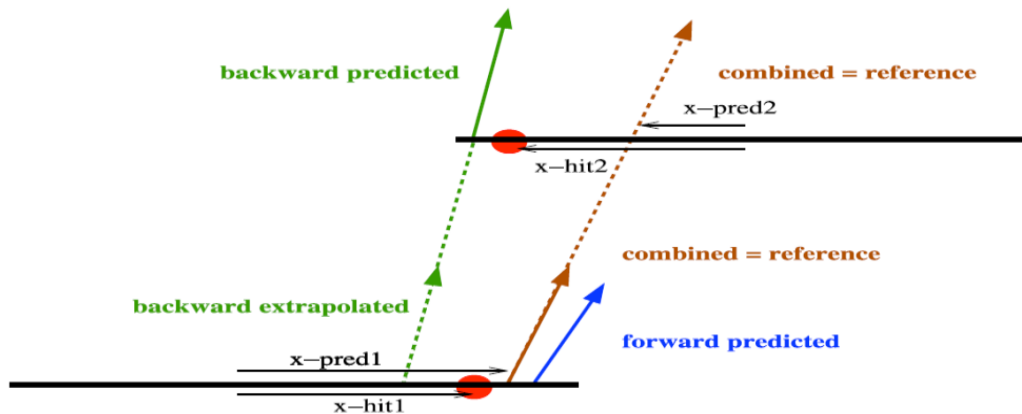
- Effect on Track Reconstruction

- Position corrections now applied in hit reconstruction.
- Hits of tracks with large d_0 on module surface are most affected.
- Pixel layer 1 for forward tracks $|\eta| > 2$ (not the topic here).
- Cosmic ray tracks:
 - ♦ average track fit probability vs d_0 now almost flat.
- Relevance for overall tracking:
 - ♦ importance of cosmic ray tracks for alignment (weak modes).



After curvature correction: $\sim 5 \mu\text{m}$ offset in peak mode data. Why?

- If timing late: charge of sensor back-plane not collected.
 - Sensor appears thinner by Δd , mean shifted by $\Delta w = \Delta d/2$.
- “Back-plane” corrections for deconvolution data calibrated with 2010 data:
 - $\Delta d = 12 \mu\text{m}$ for TOB.
- Improved time alignment in 2011: $3 \pm 1 \text{ ns}$ in TOB.
- “Back-plane” correction not re-calibrated: tension peak vs deco.
- Alignment dominated by deconvolution mode data.
 - Offset remains for peak mode data.



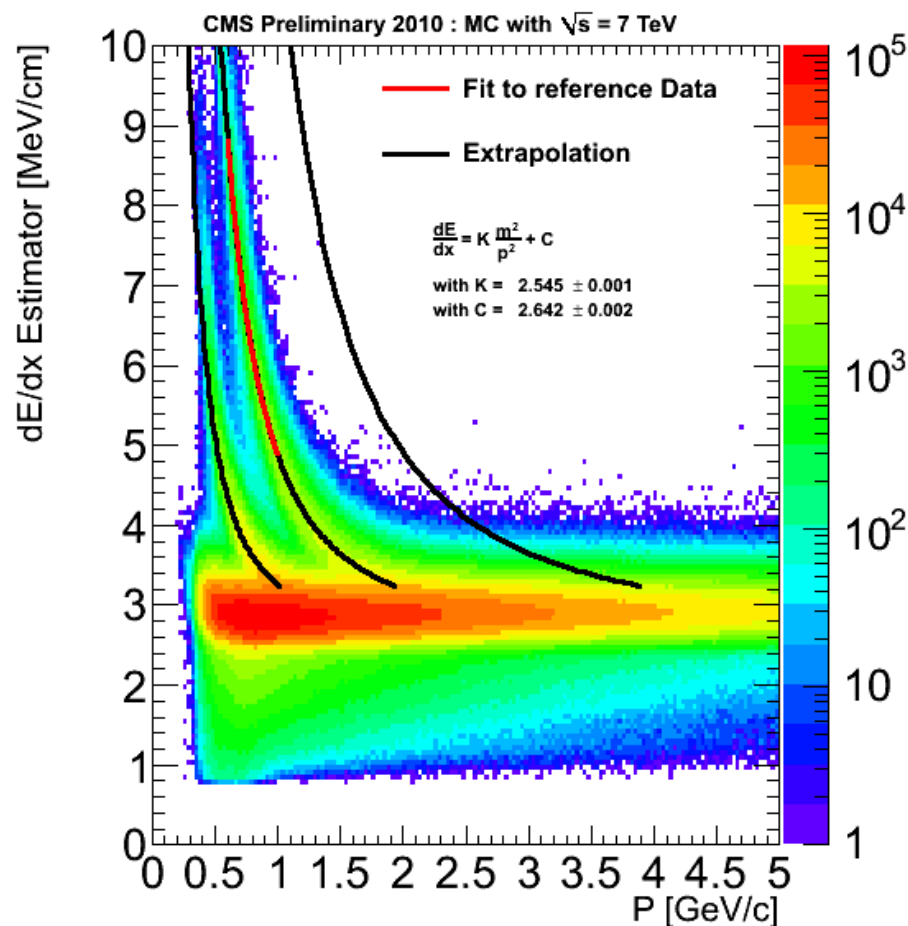
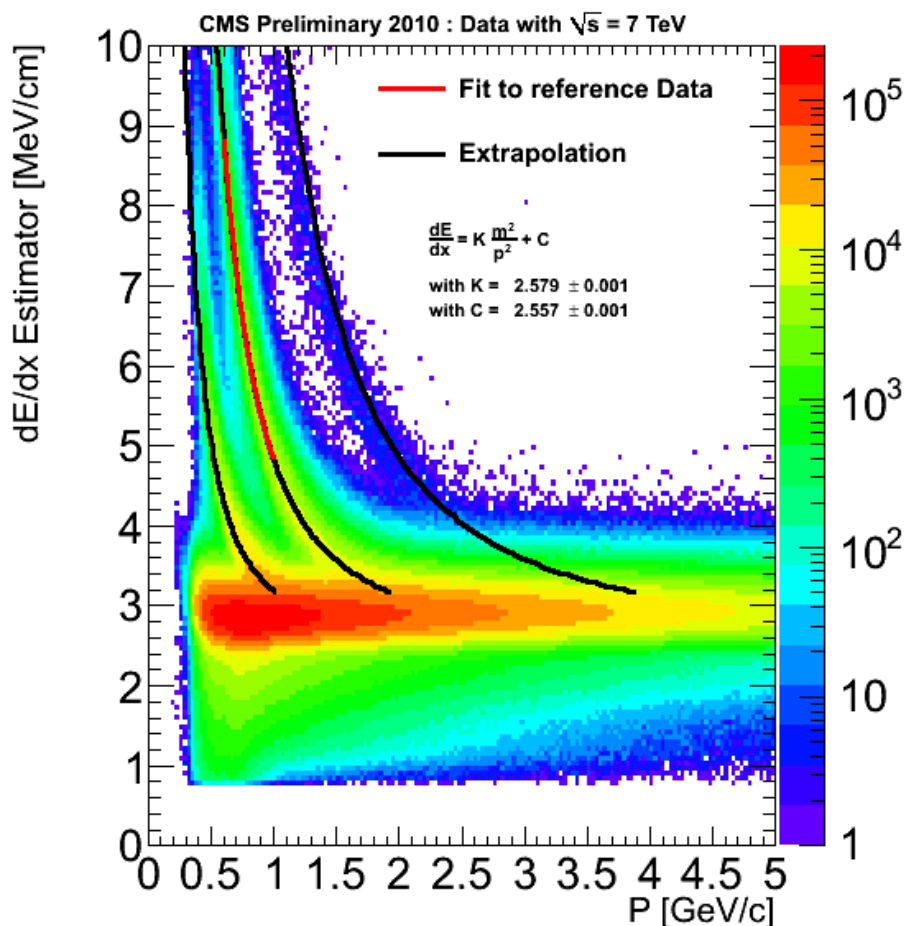
- Using Hits in Module Overlaps
 - Track angle $\psi < 10^\circ$
 - Results shown for TIB and TOB layers with pitches:
 - TIB L1+2 80 μm
 - TIB L3+4 120 μm
 - TOB L5+6 122 μm
 - TOB L1-4 183 μm
 - Values below binary resolutions.

- We can determine an estimate for the most probable dE/dx value based on the measurements in the strip tracker modules traversed by a track, ie :

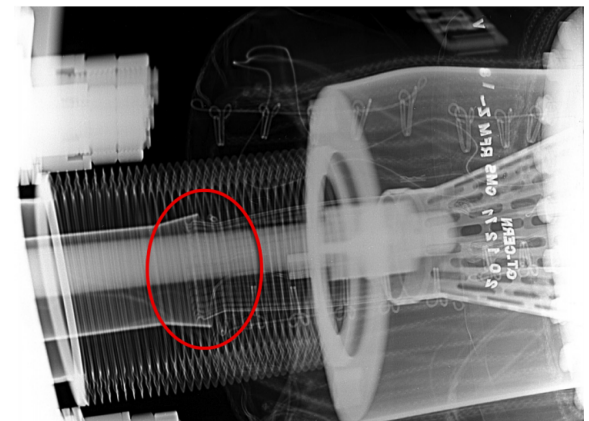
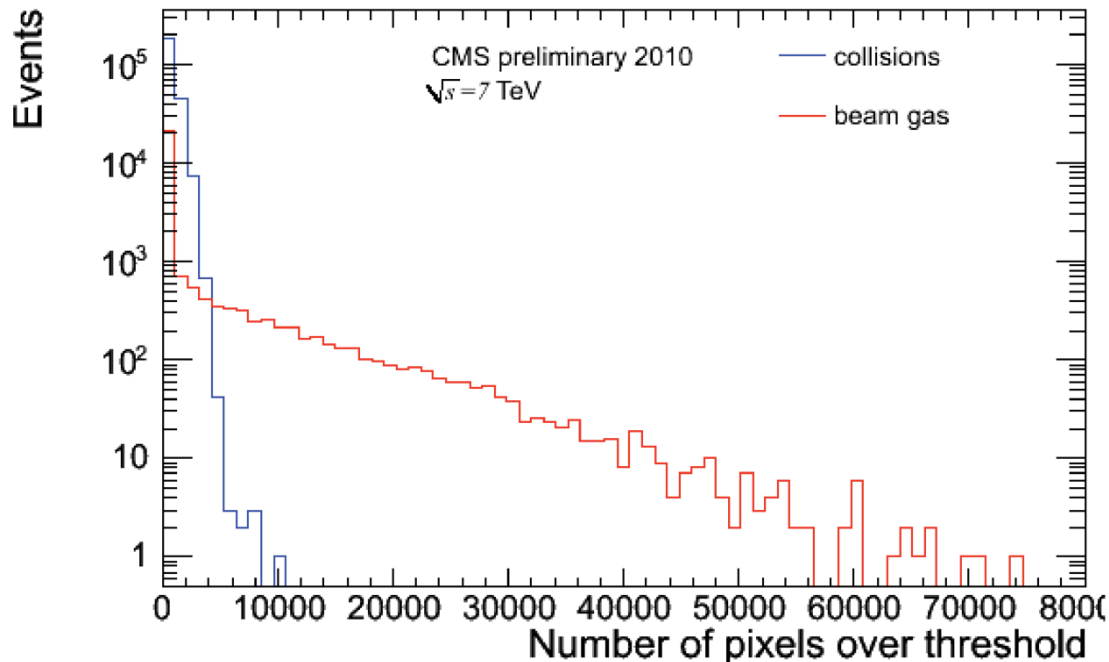
$$\frac{dE}{dx} = \left(\frac{1}{N} \sum_{i=1}^N \frac{1}{c_i^2} \right)^{-1/2}$$

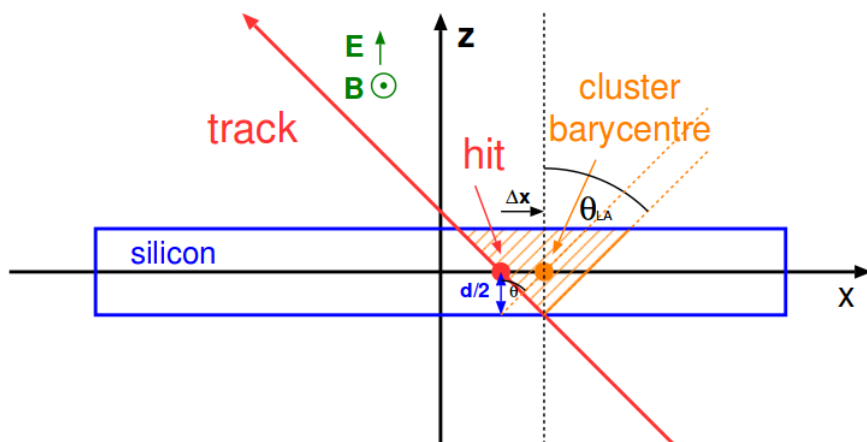
Where c_i is the charge, per unit path length of silicon, of the i th hit associated to the track

- Kaon and Proton bands are well visible in both the Data and MC.



- Beam-gas interactions: particles flying along z direction graze BPix modules, creating many hits
- Major issue during 2010: important source of downtime
- Solved with “busy mechanism”:
 - Stop triggers until channel can catch up
 - Further optimization done on data acquisition settings and firmware to minimize dead time from mechanism
- LHC joint 18.5m from interaction point fixed during 2011-2012 shutdown
 - significant improvement

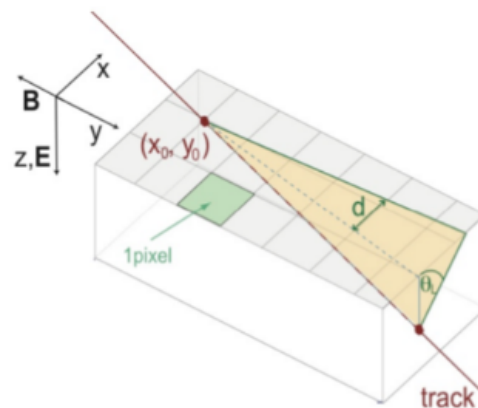




- Charge drift in B-field affects the measured hit position: $x = \tan(\theta_{LA}^{shift}) \cdot d/2$

- To correct this effect most precisely: Lorentz angle θ_{LA}^{shift} calibration integrated in MILLEPEDE II alignment procedure.
- B-on and B-off data used simultaneously in alignment to disentangle calibration and alignment effects.
- Used 60 million tracks from full 2012 data: tracks of isolated muons, $Z \rightarrow \mu\mu$, cosmic ray muons (B-on and B-off), low p_t , B-off, pp data from August 2012.
- Lorentz angle in pixel barrel calibrated with granularity of:
 - 24 spatial parameters (3 layers x 8 rings)
 - 65 periods in time.

- Charge carriers production depth and displacement in local x estimated from track parameters
- Using well reconstructed tracks \rightarrow path through detector well known
- Obtain the drift distance of the electrons created at certain depth
- Tracks with shallow impact ("grazing") angle used
- Averaged over many tracks – drift distance over production depth
- Fitted over the depth of the detector excluding edges
- $\tan(\theta_{LA}) = \text{slope}$



- Distortions of the tracker geometry can lead to a bias in the reconstructed track curvature $\kappa_{\mu \pm} \approx 1/p_T$
- Investigated using the reconstructed $Z \rightarrow \mu\mu$ mass, as a function of the muon direction and separating μ^+ and μ^- (since curvature bias has opposite effect on their p_T)
- Invariant mass distribution is fitted to a Breit-Wigner convoluted with a Crystal ball function (i.e. taking into account the finite track resolution and the radiative tail) for the signal plus an exponential background.
(Fit range is 75–105 GeV/c^2 , Z^0 width fixed to PDG value of 2.495 GeV/c^2 .)

